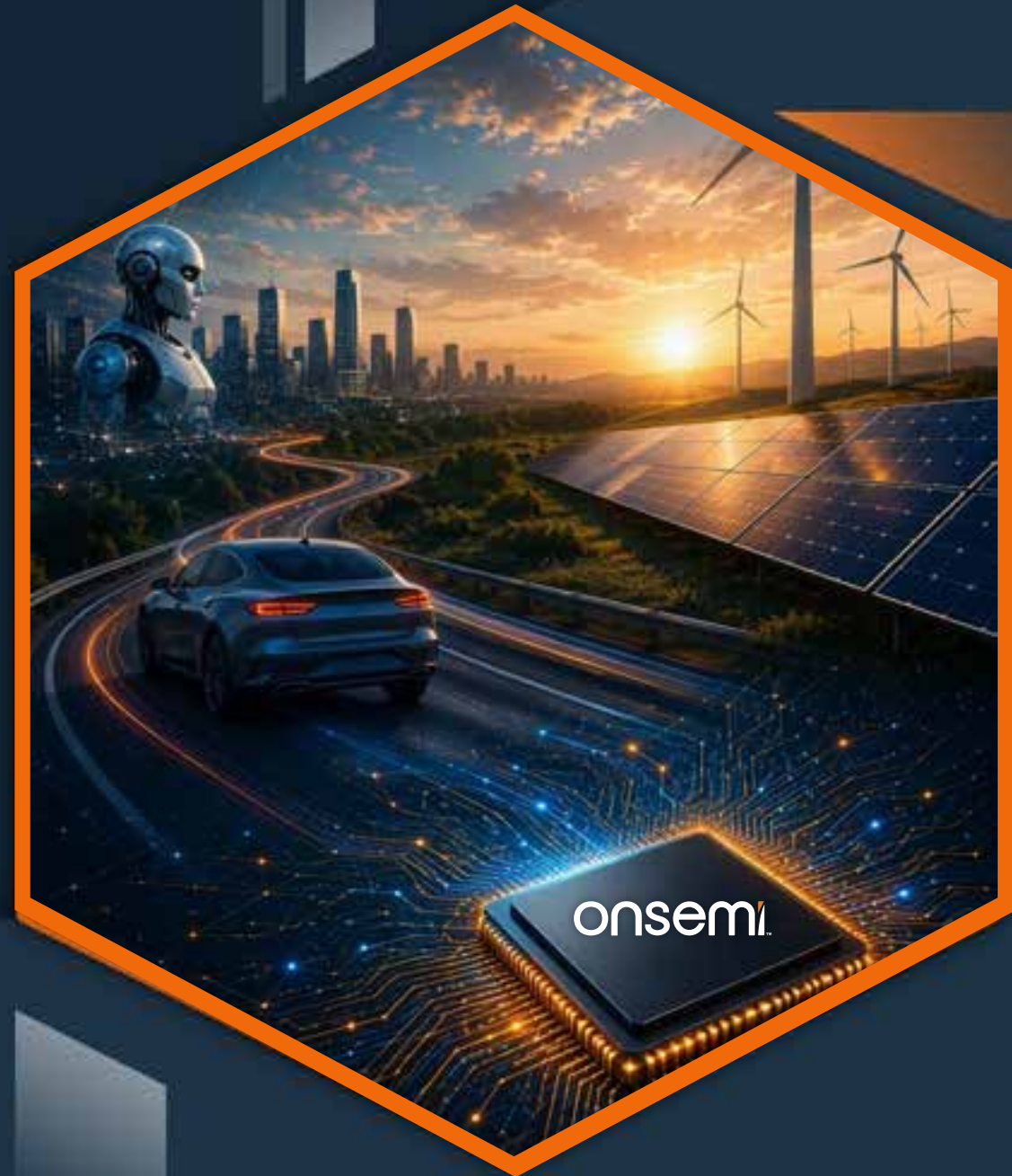




Powering a Smarter World

September 16, 2026



Cautionary Note Regarding Forward-Looking Statements



This communication relates to a proposed business combination transaction between Synaptics Incorporated (“Synaptics”) and ON Semiconductor Corporation (“onsemi”). This communication includes forward-looking statements within the meaning of Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended. All statements, other than statements of historical facts, included or incorporated in this communication could be deemed forward-looking statements, particularly statements about future financial performance and forward-looking financial guidance. These forward-looking statements are based on Synaptics’ and onsemi’s current expectations, estimates and projections about the expected date of closing of the proposed transaction and the potential benefits thereof, their respective businesses and industries, management’s beliefs and certain assumptions made by Synaptics and onsemi, all of which are subject to change. Some of these forward-looking statements can be identified by the use of forward-looking words such as “believes,” “expects,” “may,” “will,” “should,” “seeks,” “approximately,” “intends,” “plans,” “estimates,” “projects,” “strategy,” “anticipates,” or “Target,” or the negative of those words; other comparable terminology that convey uncertainty of future events or outcomes; or by discussions of strategy, plans, projections or intentions.

These forward-looking statements involve known and unknown risks and uncertainties, which may cause Synaptics’ or onsemi’s actual results and performance to be materially different from those expressed or implied in the forward-looking statements. Factors and risks that may impact future results and performance include, but are not limited to, the following factors: (1) the risk that the conditions to the closing of the transaction are not satisfied, including the risk that required approvals from regulators or the stockholders of Synaptics for the transaction are not obtained; (2) litigation relating to the transaction; (3) uncertainties as to the timing of the consummation of the transaction and the ability of each party to consummate the transaction; (4) risks that the proposed transaction disrupts the current plans and operations of Synaptics or onsemi, including restrictions during the pendency of the transaction that may impact the ability to pursue certain business opportunities or strategic transactions; (5) the ability of Synaptics and onsemi to retain and hire key personnel; (6) competitive responses to the proposed transaction; (7) unexpected costs, charges or expenses resulting from the transaction; (8) potential adverse reactions or changes to business relationships resulting from the announcement or completion of the transaction; (9) the combined companies’ ability to achieve the growth prospects and synergies expected from the transaction, as well as delays, challenges and expenses associated with integrating the combined companies’ existing businesses; (10) uncertainty as to the long-term value of onsemi’s common stock; (11) legislative, regulatory and economic developments; and (12) unpredictability and severity of catastrophic events, including, but not limited to, acts of terrorism or outbreak of war or hostilities, as well as Synaptics’ and onsemi’s response to any of the aforementioned factors. These risks, as well as other risks associated with the proposed transaction, are more fully discussed in the proxy statement/prospectus that is included in the Registration Statement on Form S-4 that has been filed with the Securities and Exchange Commission (“SEC”) in connection with the proposed transaction. While the list of factors presented here is considered representative, no such list should be considered to be a complete statement of all potential risks and uncertainties. Unlisted factors may present significant additional obstacles to the realization of forward-looking statements.

In addition, actual results are subject to other risks and uncertainties that relate more broadly to Synaptics’ overall business, including those more fully described in Synaptics’ filings with the SEC including its annual report on Form 10-K for the fiscal year ended June 27, 2026, and its quarterly reports filed on Form 10-Q for the current fiscal year, and onsemi’s overall business and financial condition, including those more fully described in onsemi’s filings with the SEC including its annual report on Form 10-K for the fiscal year ended December 31, 2025, and its quarterly reports filed on Form 10-Q for its current fiscal year.

Investing in onsemi’s or Synaptics’ securities involves a high degree of risk and uncertainty, and readers should carefully consider the trends, risks, and uncertainties described in this communication and other SEC filings of onsemi and Synaptics (including those referenced above) before making any investment decision. If any of these trends, risks, or uncertainties actually occurs or continues, the business, financial condition, or operating results of either or both companies could be materially adversely affected, the trading prices of each company’s securities could decline, and investors could lose all or part of their investment. Forward-looking statements are not guarantees of performance, and speak only as of the date made, and neither onsemi, nor Synaptics nor the management of either entity undertakes any obligation to update or revise any forward-looking statements, except as may be required by law. All forward-looking statements attributable to onsemi, Synaptics, or persons acting on behalf of either company are expressly qualified in their entirety by this cautionary statement.

This is not an offer or solicitation. For additional information, please reference slides 100 – 101.

Use of Non-GAAP Financial Measures



This presentation contains historical non-GAAP financial measures including, among others, free cash flow (FCF) and FCF margin, non-GAAP gross margin and non-GAAP operating margin. This presentation also contains forward looking non-GAAP financial measures, some of which are adjusted for certain special items. These special items are out of our control and could change significantly from period to period. As a result, we are not able to reasonably estimate and separately present the individual impact of these special items, and we are similarly unable to provide a reconciliation of the non-GAAP measures. The reconciliation that is unavailable would include a forward-looking income statement, balance sheet, and statement of cash flows prepared in accordance with GAAP. We believe these non-GAAP measures provide important supplemental information to investors. We use these measures, together with GAAP measures, for internal managerial purposes and as a means to evaluate period-to-period comparisons. However, we do not, and you should not, rely on non-GAAP financial measures alone as measures of our performance. In addition, because non-GAAP financial measures are not standardized, it may not be possible to compare these financial measures with other companies' non-GAAP financial measures, even if they have similar names.

For a reconciliation of historical non-GAAP financial measures to GAAP, please see the Appendix on slide 90.

Powering a Smarter World

TOPIC

PRESENTER

**Charting a Path to Power
the Next Decade of Innovation**

Hassane El-Khoury
President & CEO

Powering the AI Revolution

Achyut Shah
Group President, Power Solutions Group

**Expanding the Core:
Automotive and Industrial**

Sudhir Gopalswamy
Group President,
Analog & Mixed-Signal and Intelligent Sensing Groups

**Turning Technology Leadership into
Durable Financial Performance**

Thad Trent
Executive Vice President & CFO

Q&A

All



Charting a Path to Power the Next Decade of Innovation

Hassane El-Khoury
President and CEO

Every foundational technology
eventually encounters a physical limit

We've reached it.

onsemi[®]

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A Foundational Technology Is Not an Invention... onsemi

IT'S A LAYER

It's not the product



Three Signatures of a Foundational Technology

1  WIDESPREAD IMPACT

2  CONTINUOUS IMPROVEMENT

3  FOUNDATIONAL DEPENDENCY

A force multiplier...
...for human progress.

It's the foundation

Foundational Technology Layer:
Disruptor across all markets

 Automotive  Industrial  AI  Consumer

 EXPANDS POSSIBILITY

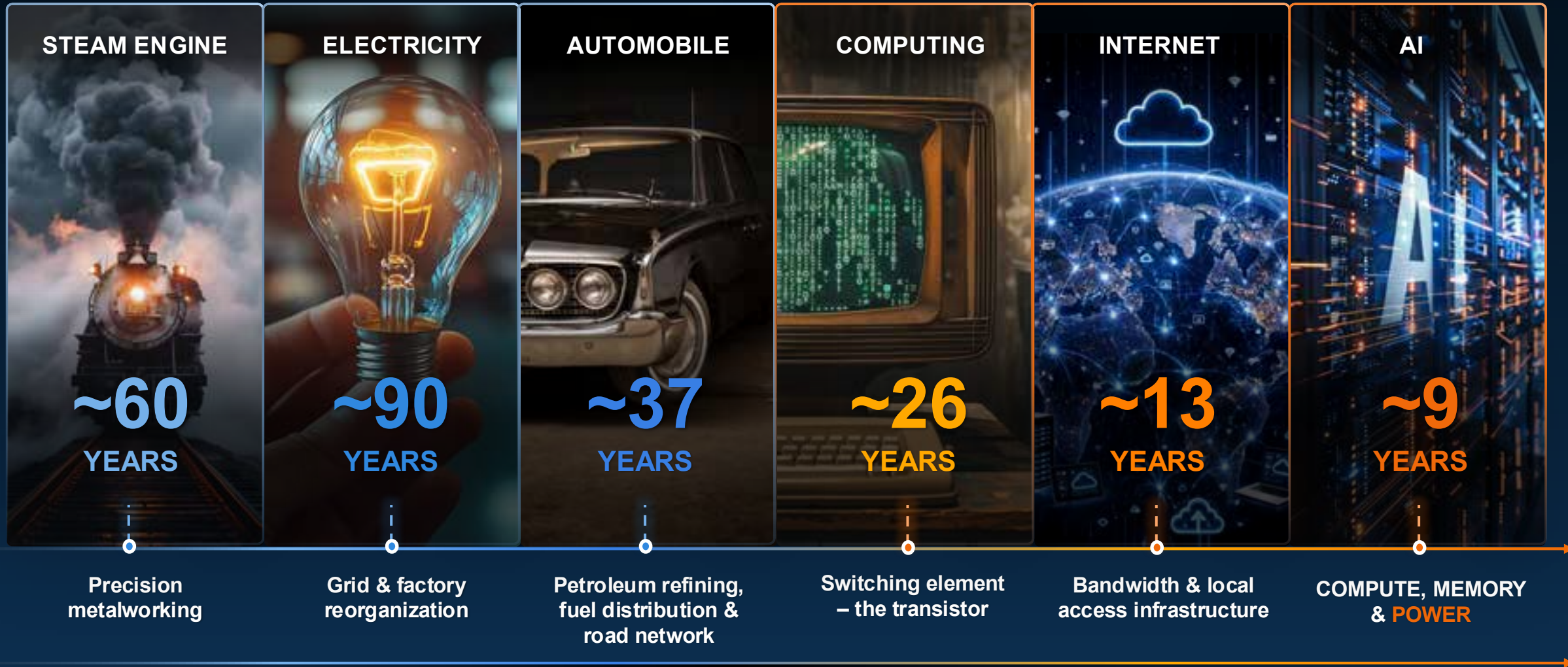
 ELEVATES QUALITY OF LIFE

 ENABLES SUSTAINABILITY

 UNLOCKS THE NEXT FRONTIER

The Future is Arriving Faster Than Ever

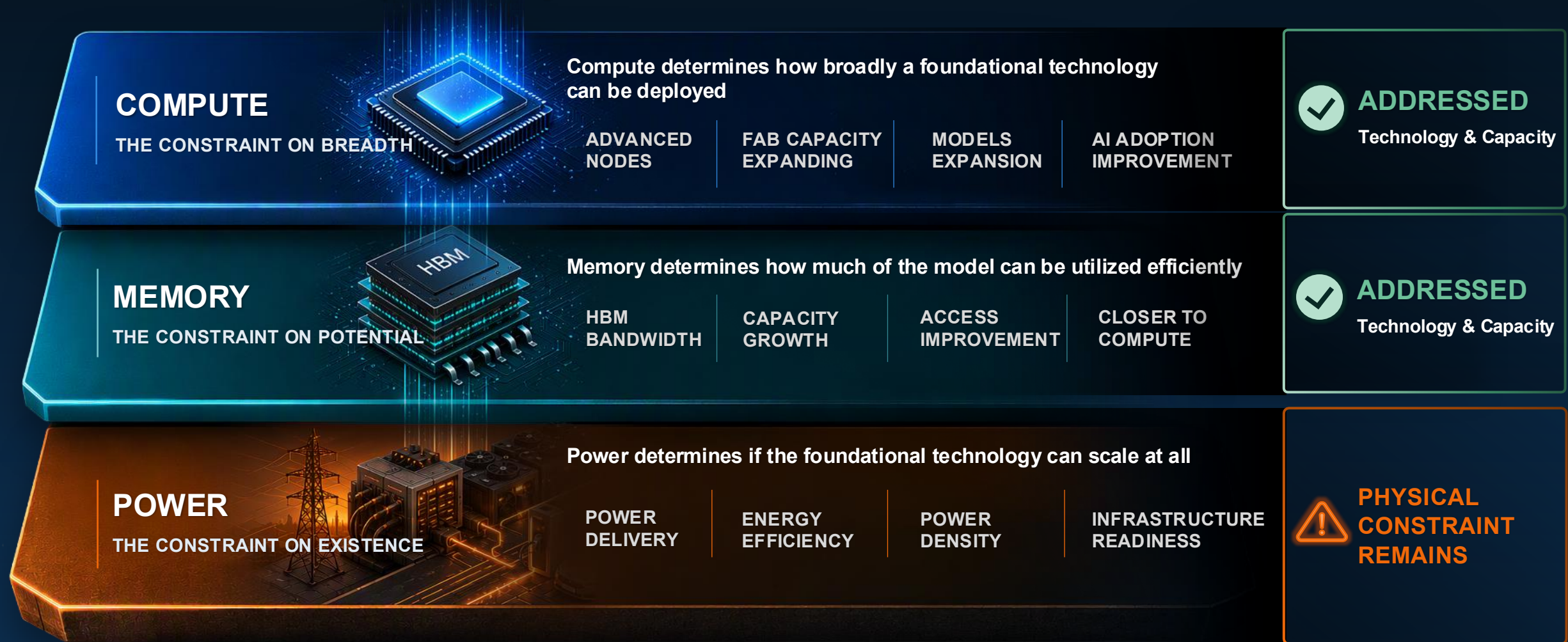
onsemi



Every Foundational Technology Was Gated By A Physical Constraint

Physical Constraint Ladder

Each constraint sits deeper in the system. **Each is harder to move.**



MORE PHYSICAL

Until power density breaks through, the AI revolution is limited

More Power Isn't Enough. The World Needs Better Power.

onsemi

YESTERDAY: POWER SUPPORTED WORK



Factories

Predictable
operations



Appliances

Intermittent
usage



Buildings

Managed
consumption



**Conventional
Vehicles**

Mechanical
systems

Power was relatively predictable
and tolerant of inefficiency

THE CHALLENGE HAS CHANGED

POWER MUST BE



More
Efficient



More
Dense



More
Reliable



More
Precise



More
Autonomous



More
Scalable

TOMORROW: POWER ENABLES INTELLIGENCE



INTELLIGENCE

AI Data Centers

Robotics & Humanoids

Autonomous Vehicles

Smart Infrastructure

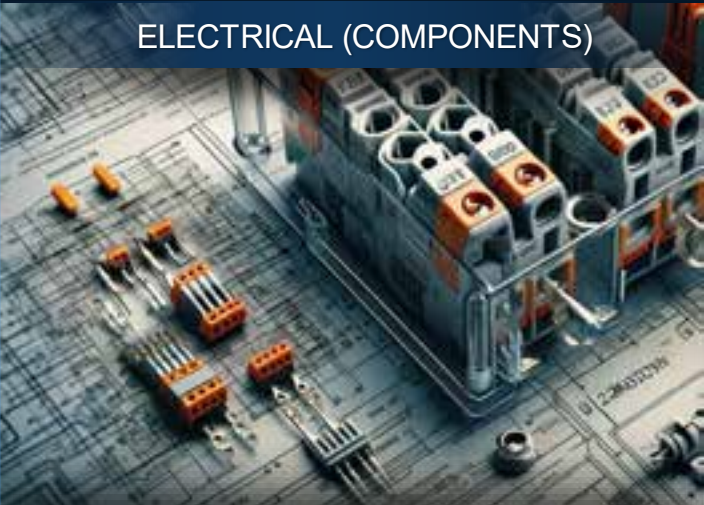
Smart Factories

Edge AI Systems

**Power is always on, always
connected, always at peak, and
critical to performance**

WE SOLVED THE POWER OF YESTERDAY

ELECTRICAL (COMPONENTS)



More watts → Bigger → Centralized

Electrical



Convert, control
and distribute
power efficiently

Thermal



Move heat
before it limits
performance

Mechanical



Withstand
stress and
enable reliability

Physical



Design within
the limits of
physics

POWER OF TODAY

MULTI-PHYSICS SYSTEMS



More watts → Smaller → Distributed

MORE POWER. LESS SPACE. HIGHER EFFICIENCY. UNMATCHED RELIABILITY.

⚡ WE SOLVED POWER



NOW WE SOLVE POWER DENSITY

System Requirements are Moving in Opposite Directions

What the customer asks for

- ▲ **Input voltage** Increasing
- ▼ **Output voltage** Decreasing
- ▲ **Power** Increasing
- ▼ **Physical space** Constrained
- ◆ **Cost** Always challenged



Electrical + Thermal + Mechanical + Physical
Nothing on the market closes all at once

And the problems only get harder across end markets and applications

AI Data Center

800V and higher → 6V or less

Industrial: Solid-State Transformer

13.8kV → 34.5kV

Automotive: xEV

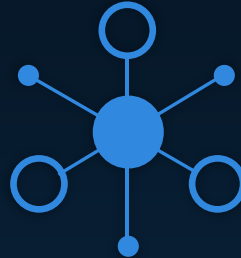
400V → 900V+

The Constraint has Changed. So did we.

onsemi

FROM SOLVING POWER

Efficiency • Conversion • Components • Scale

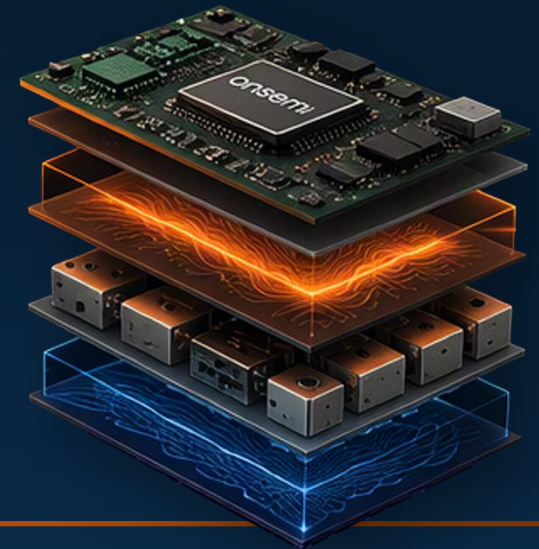


Power density is not
solved by one device

It requires a
different company

TO SOLVING POWER DENSITY

Electrical • Thermal • Mechanical • Physical

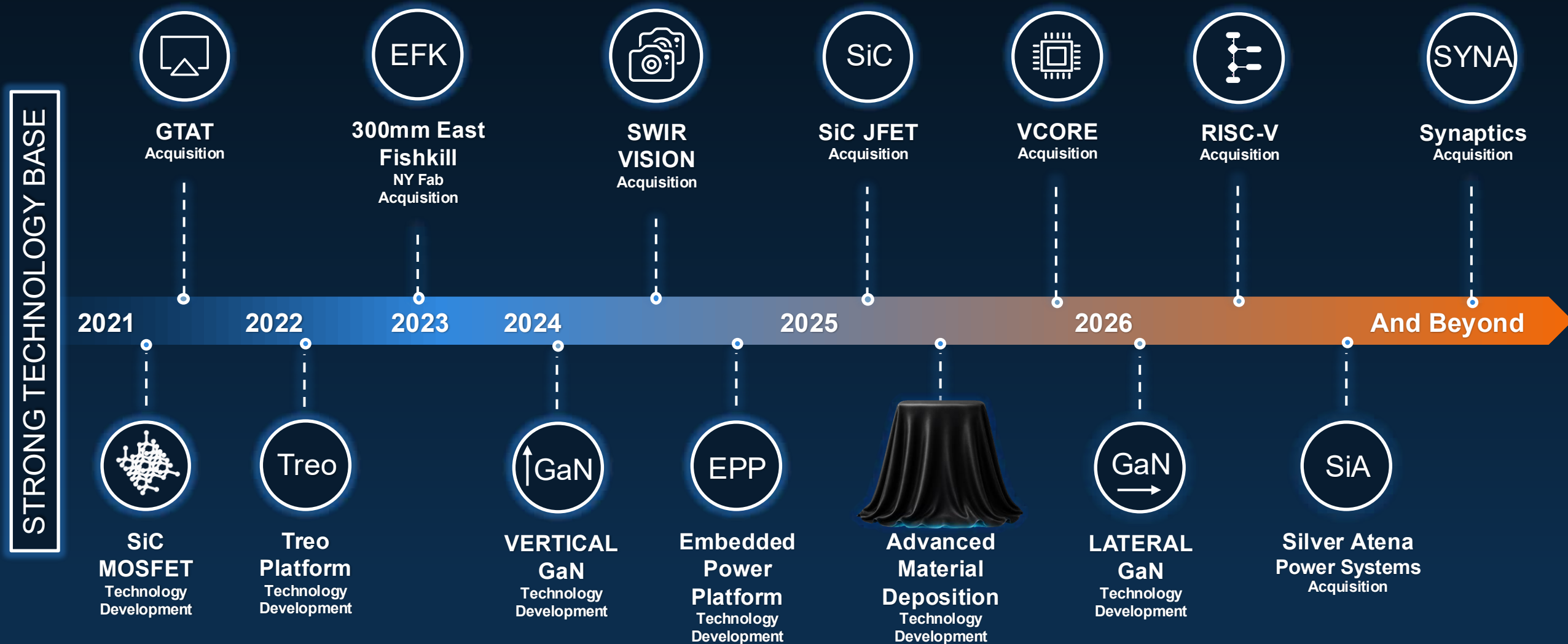


onsemi

onsemi is a fundamentally different company
for a fundamentally different problem: **Power Density**

onsemi STRATEGIC ACTIONS

onsemi



Synaptics **Extends** the onsemi Portfolio...

onsemi

onsemi

POWER

Efficient power conversion

- Silicon to wide-bandgap
- Power management
- Power protection

onsemi + Synaptics

SENSE

Perception of the physical world

- Image sensors
- Ultrasonic & Inductive position sensors
- HMI & Tactile sensing

onsemi

CONTROL

Precise actuation & control

- Analog & mixed-signal ICs
- Drivers
- Controllers

+ Synaptics

CONNECTED COMPUTE

Edge intelligence & connectivity

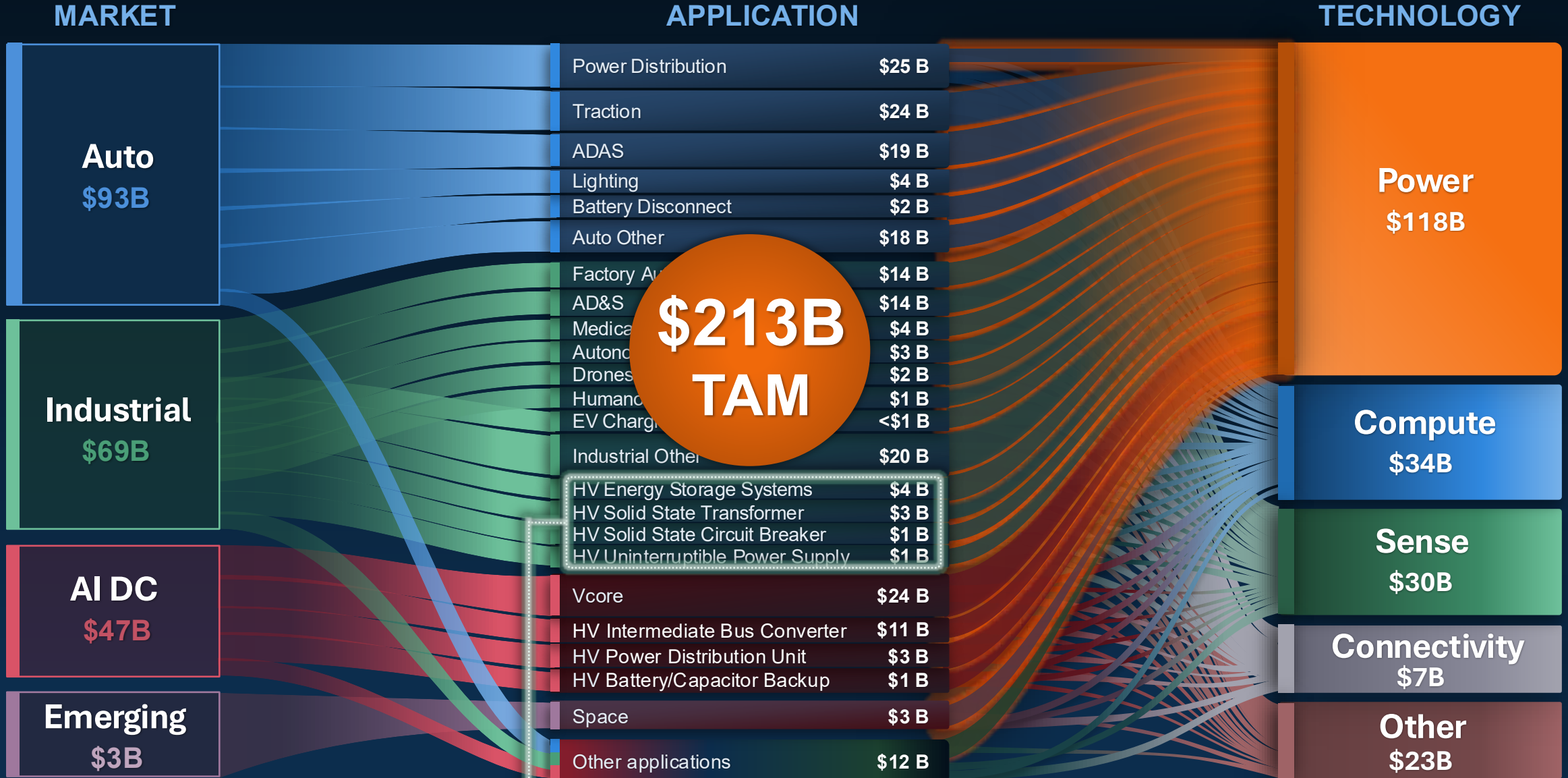
- Single pair ethernet
- AI-First Compute
- Connectivity: Wi-Fi / BLE / Thread

...completing the **Four Pillars of Physical AI**

Machines that sense, decide, act and adapt

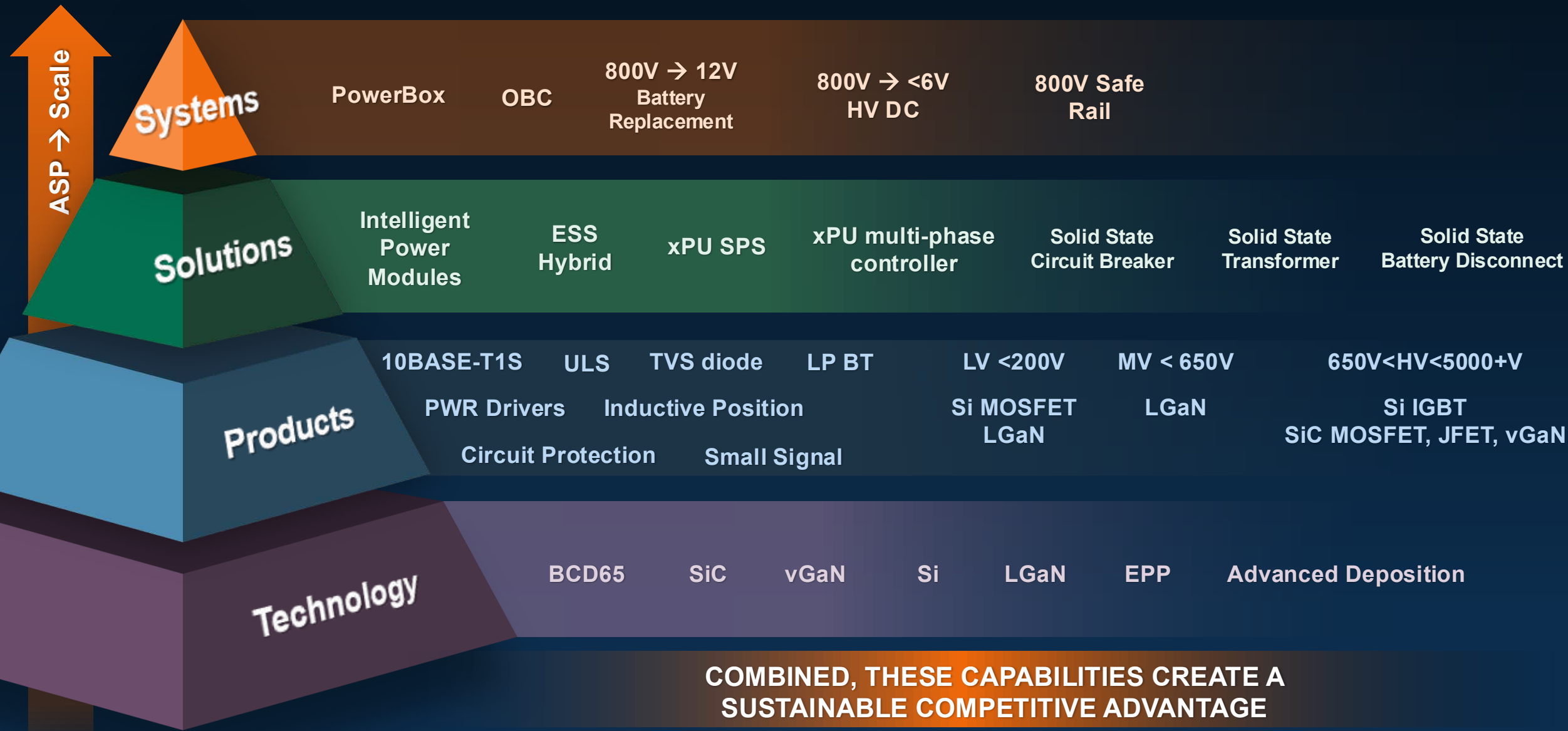
Every Market Converges on Power

onsemi



AI Halo - \$9B of industrial built to support data centers

Delivering The Value Stack



We Must Change the Power Systems Paradigm...



...by Introducing Technologies to Address the Constraints...

onsemi



HV

THE DEVICE

Treo

THE INTELLIGENCE

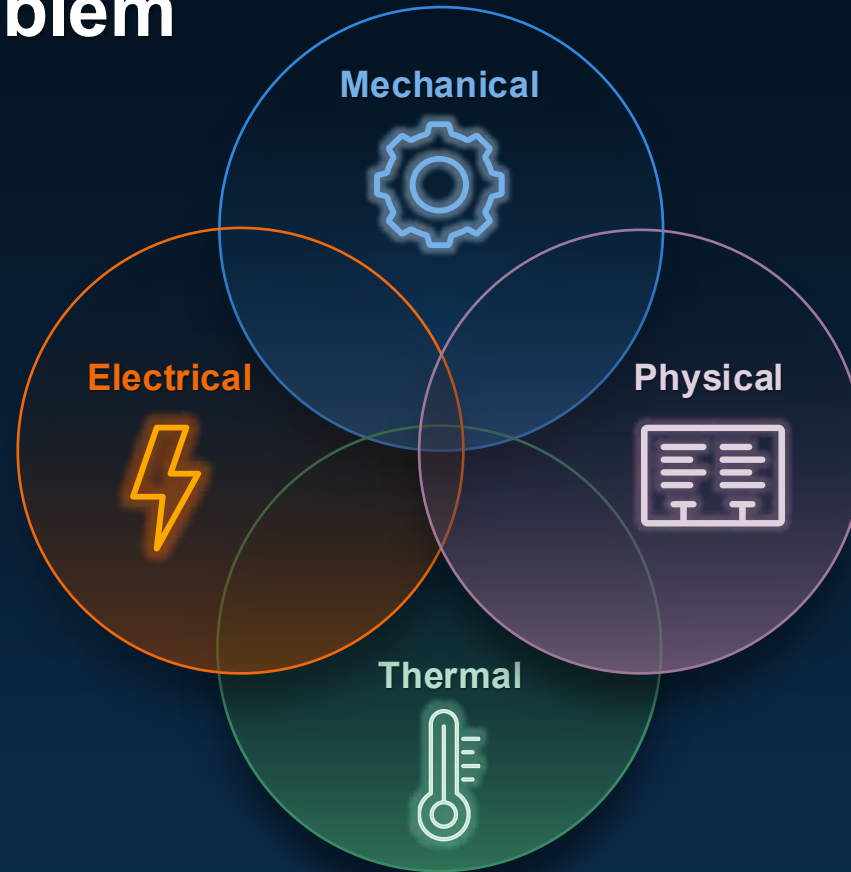
EPP

THE INTEGRATION

Supported by a complete portfolio of differentiated **Power** and **Sensing** technologies

...And Creating the Disruption Necessary to Unlock the **Power Density** Problem

onsemi



HV

THE DEVICE

Treo

THE INTELLIGENCE

EPP

THE INTEGRATION

Supported by a complete portfolio of differentiated **Power** and **Sensing** technologies

onsemi has Every HV Option to Close the Gap

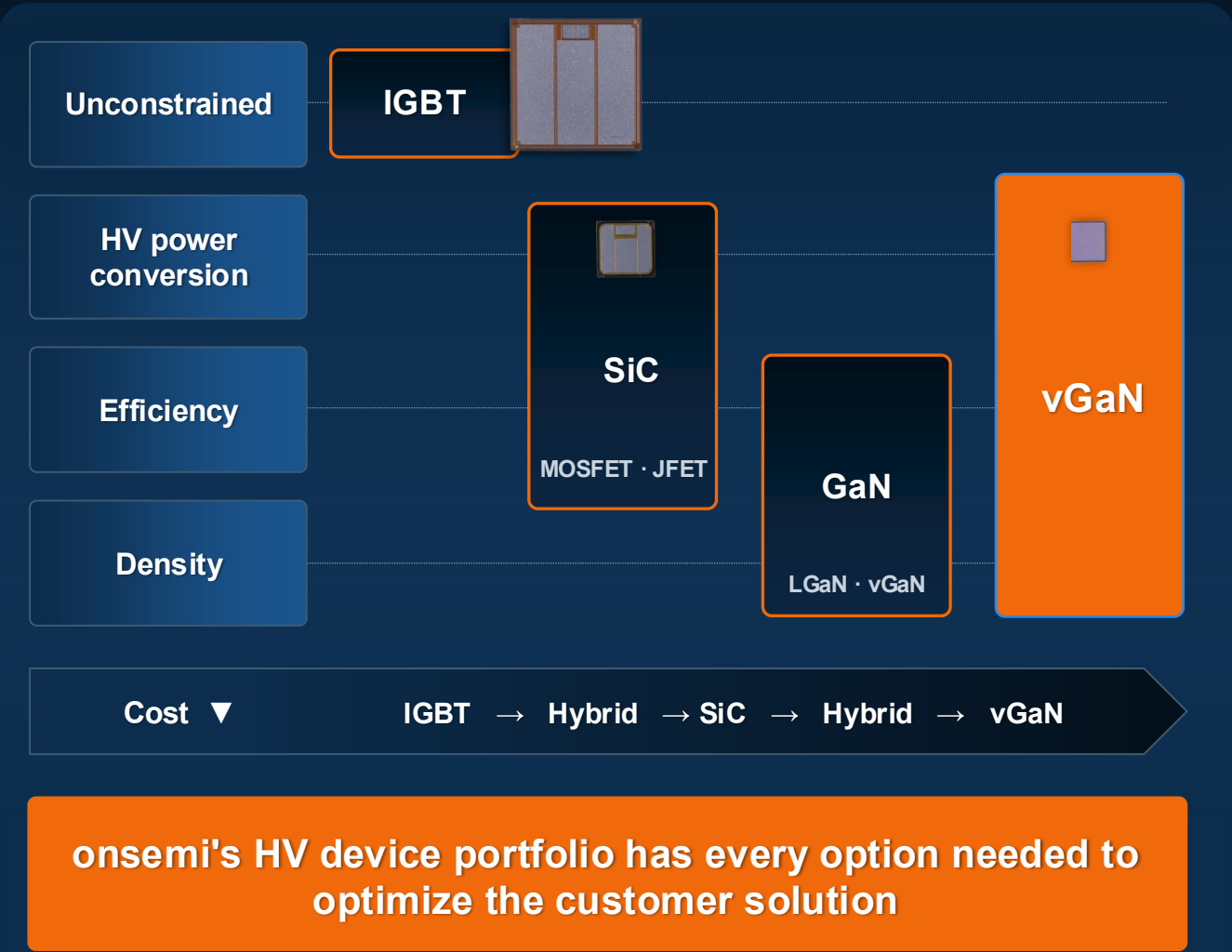


HV

Treo

EPP

Power and Sense Portfolio



vGaN solution...And it's ready

Syracuse, NY - onsemi vGaN R&D and manufacturing fab, in production today

66,000 sq ft

14-acre site

20,000 sq ft

clean room

\$40M+

tools & machines

\$120M+

investment

Treo Platform

Communications Subsystem

Application-Specific Interfaces

Power Subsystem

Power
Control

DC-DC

Driver

Power
FET

Power Subsystem

High-Performance
AFE

Low-Power
AFE

Compute & System Resources Subsystem

Compute

Voltage/Clock

Standard I/O

Memory

Test

Peripherals

BCD 65nm

Technology Process

Best performance & power
Advanced feature integration

Industry's Widest Voltage Range: 1 - 90V

Highest integration
Auto 48V transition

Modular Architecture

Broad onsemi portfolio
Fast time-to-market

The **onsemi Treo Platform** is the **most advanced** in the industry, **enabling winning** analog and mixed-signal products, for next generation applications

2024

Products Sampling

- Low-Power AFE ASIC**
Medical
- Ultrasonic Sensor ASIC**
Automotive
- Test Equipment Signal Processor ASIC**
Industrial
- 10BASE-T1S MAC-PHY**
Automotive, Industrial
- Multi-Phase Controller**
AI / Client
- LDO Regulators**
Mass Market
- Voltage Level Translators**
Mass Market
- Bus Switches / Muxes**
Mass Market

2025

Products Sampling

- 10BASE-T1S RCP**
Automotive, Industrial
- Smart LED Driver Chipset**
Automotive
- Ultrasonic Base Product**
Automotive
- 2-Ch Low-Power AFE ASIC**
Medical
- LIN Transceiver**
Automotive
- Platform MCU**
Automotive, Industrial, AI / Client, Mass Market
- Precision Current-Sense / Comparators**
Automotive, Industrial, Mass Market
- Expanded LDO Portfolio**
Automotive, Industrial

2026

Products Sampling

- 48V SmartFET High-Side Drivers**
Automotive
- Isolated SiC Gate Driver**
Automotive / AI Data Center
- High-Perf Ultrasonic Sensor**
Automotive
- Inductive Position Sensors**
Auto (E-Pedal/Steer)
- Rain / Light Sensor Interface**
Automotive
- Ideal Diode Controller**
Automotive, Industrial, Compute
- ReRAM Non-Volatile Memory**
Automotive, Industrial, Compute
- Expanded Current-Sense**
Automotive, Mass Market
- Additional Voltage Translators**
Mass Market
- Switched-Cap Converter + LDO**
Automotive, Industrial

Introducing onsemi's Embedded Power Platform

onsemi

The silicon **becomes** the system.

EPP is the breakthrough that creates a new category of power systems.

3–5×

UNMATCHED
POWER
DENSITY

30%

HIGHEST
SYSTEM
VALUE

12 in.

STANDARD
MANUFACTURING

4 MOS

FASTEST
TIME TO
MARKET



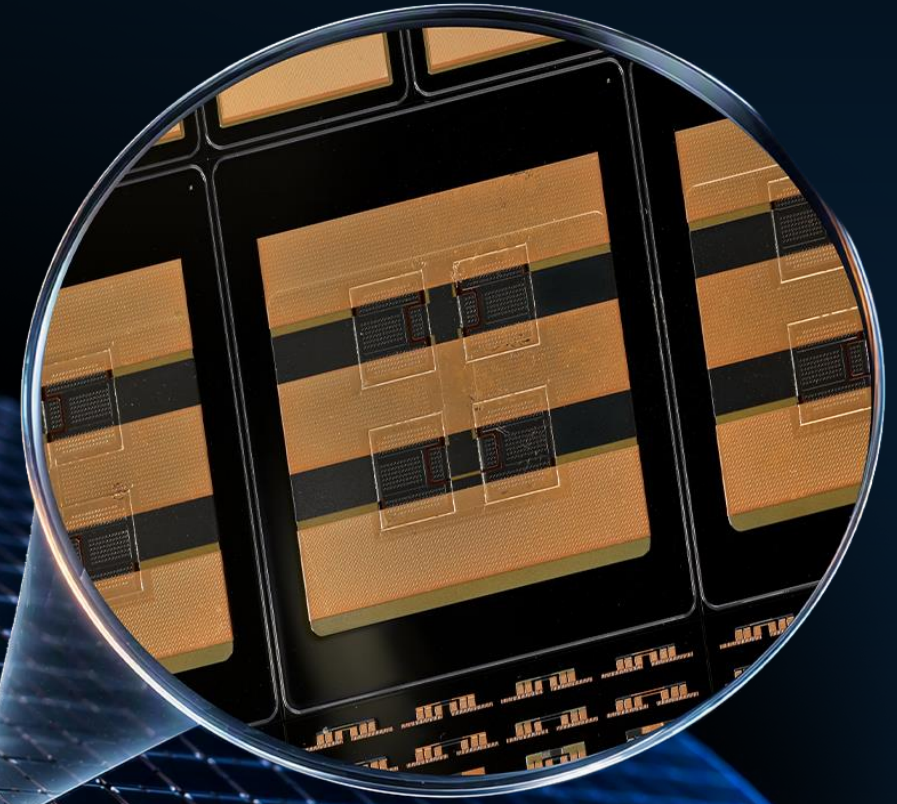
BEST-IN-CLASS
INDUCTANCE



SUPERIOR THERMAL
PERFORMANCE

Embedded Power Platform (EPP) uses the silicon wafer itself as the package, embedding heterogeneous die to deliver electrical, mechanical and thermal performance simultaneously, solving the density problem.

Not a product. A platform.

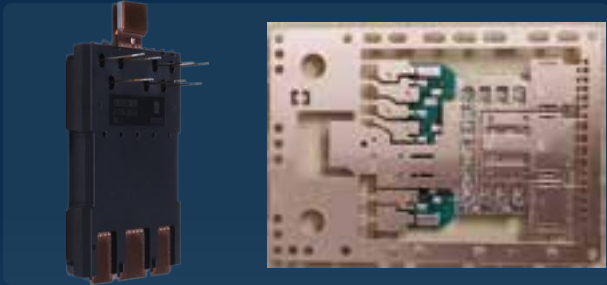


EPP Leapfrogs PCB Embedded Power

Yesterday's solutions

Lead-frame & DBC substrate (B2S)

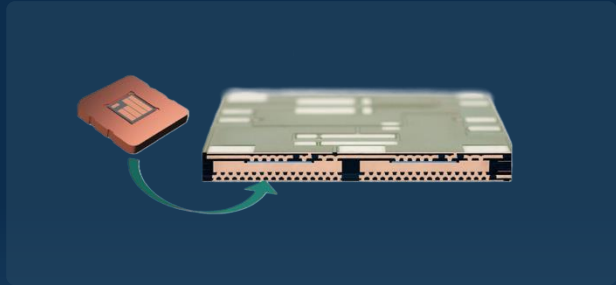
● Available today



State-of-the-art

Panel / S-Cell PCB embedding

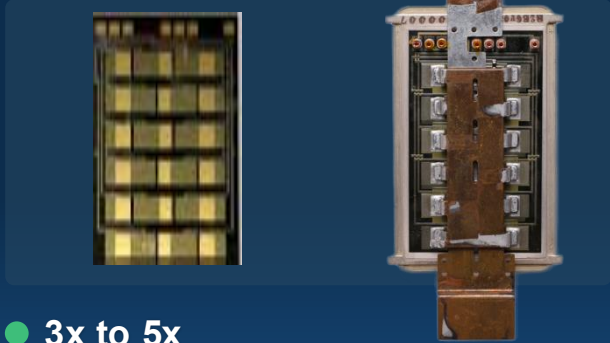
● Available today



onsemi EPP

Embedded Power Platform

● Sampling today



EVALUATION CRITERIA

Power density (area vs. B2S)	● 1x	● 1.3x	● 3x to 5x
System cost (vs. B2S)	● 1.0	● 1.1	● 0.7 – 0.8
Stray inductance	● Medium	● Low	● Lowest
Thermal path	● Bottom-side · 4 W/mK	● Bottom-side · 0.4 W/mK	● Dual-side · 148 W/mK
Device performance	● 1.0	● +5%	● +30%
Manufacturing	● Custom · high CapEx	● Custom · high CapEx	● 12" Si fab · low CapEx
Idea → production	● 12 months (6+6)	● 12 months (6+6)	● 4 months

Embedded Power Platform obsoletes the State-Of-The-Art

Delivering Value to Customers Already

< 48 hours

- 1 Customer input
Size · Voltages · efficiency
- 2 EPP Design Studio
Electrical, thermal and mechanical simulation · multi-technology

< 5 days

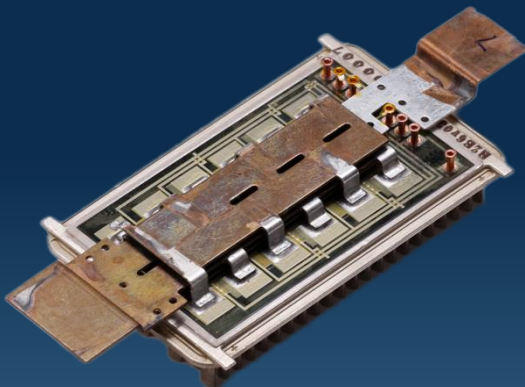
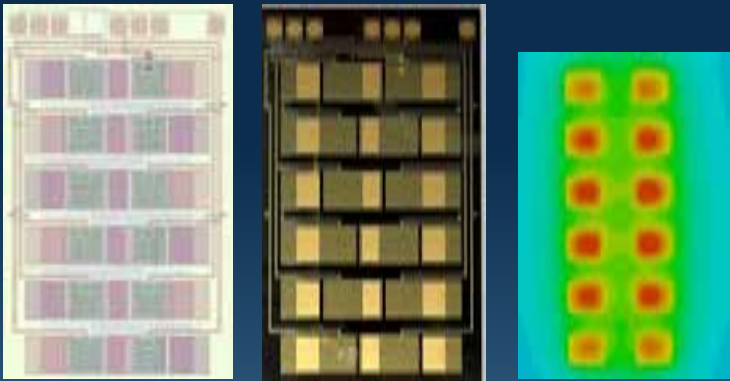
- 3 Studio output
Design · datasheet · validated models
- 4 Customer system modelling
System design and concept complete

< 3 months

- 5 No custom back-end
No new CapEx or custom tooling to bring up
- 6 Interposer manufacturing
12" silicon fab · standard process

Customer / project dependent

- 7 System integration
Validation at the customer, on the customer's schedule
- 8 Production
Wafer-level test · standard flow



Industrial
Customer

AI DC
Customer

onsemi Differentiation



Solving Problems with a Complete and Unique Suite of Capabilities

TECHNOLOGY NEEDED	onsemi	Peer 1	Peer 2	Peer 3	Peer 4
IGBT	✓	✓	×	✓	×
Silicon MOSFET	✓	✓	✓	✓	×
SiC MOSFET	✓	✓	×	✓	●
SiC JFET	✓	✓	×	×	×
Lateral GaN	✓	✓	✓	✓	✓
Small Signal and Protection	✓	×	×	×	×
Vertical GaN	✓	×	×	×	×
Treo (BCD 65nm, 1V-90V)	✓	●	●	●	×
Embedded Power Platform	✓	×	×	×	×

UNIQUE AND DEFENSIBLE COMPETITIVE POSITION

Power
1500+ patents

Vertical GaN (*GaN-on-GaN*)
Syracuse-built, 180+ patents,
700 V & 1200 V sampling.

EPP
EFK-built, 60+ patents.
Sampling Auto and AI DC

The constraint is a system constraint and must be answered at the **device**, the **intelligence** and the **integration** layer

HV

THE DEVICE

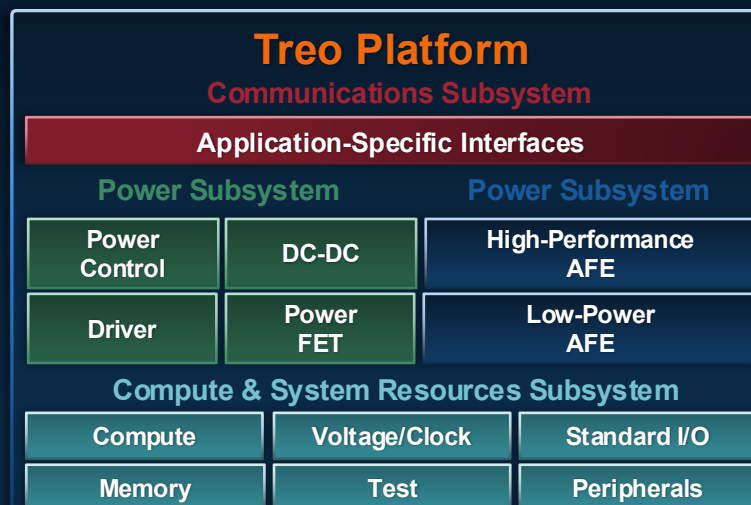
Technology for every power problem



TREO

THE INTELLIGENCE

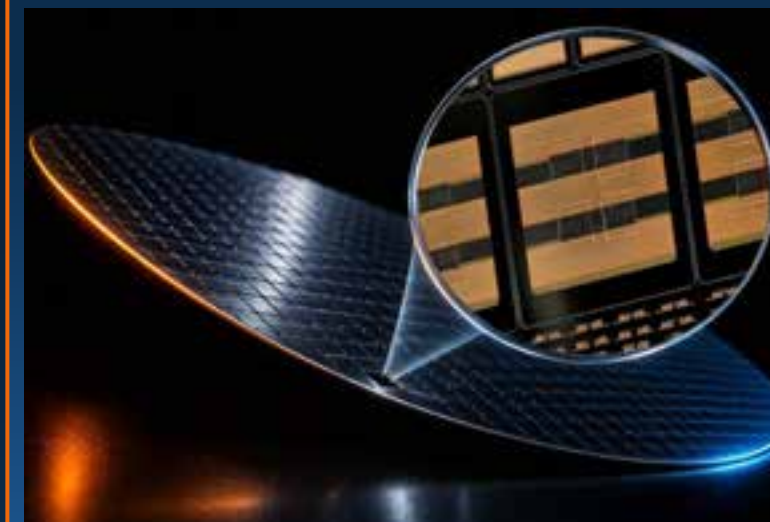
Analog and mixed-signal platform



EPP

THE INTEGRATION

Silicon as the system



The requirements do not converge on their own
onsemi makes them converge. We solve **Power Density** at every level.



onsemi: Powering the AI Revolution

Achyut Shah
Group President, Power Solutions Group



Electrical • Thermal • Mechanical • Physical

“ The bottleneck has shifted from chips to **power**. ”

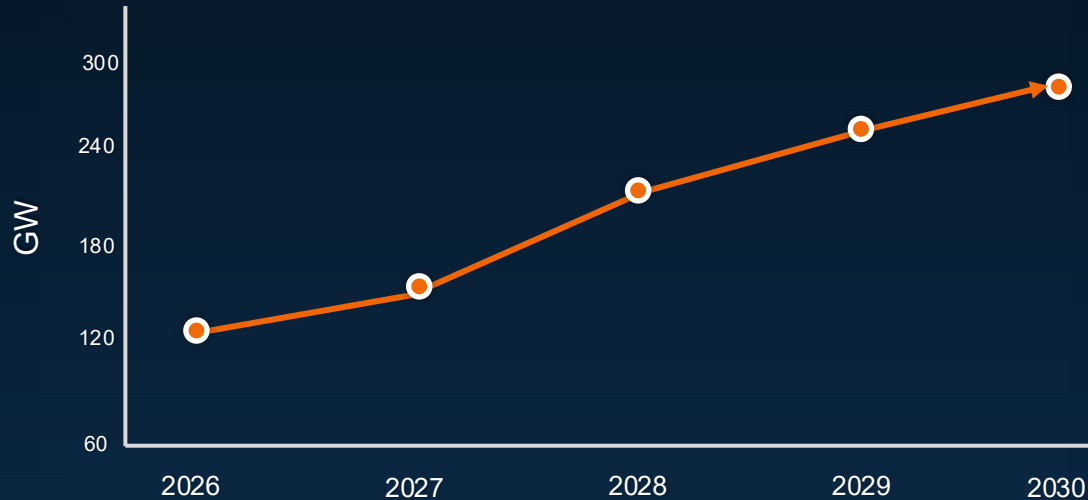


Jensen Huang
Founder, President & CEO

Increased Power Demand Creates Architectural Challenges

Cumulative Data Center Power Consumption

Bank of America



“800 VDC architecture: a single AC-to-800VDC conversion, distributed and used directly by the compute rack.”

**Goldman
Sachs**

“1,000 homes of power in a filing cabinet.”

“Power, not GPUs, is the limiting factor for AI data centers... the **power density challenge is creating a fundamental architectural crisis at the rack level. The companies that solve this first will shape the competitive landscape for years to come.”**

– Roland Berger

Power Density Redefines Economics of Compute

onsemi[®]

A circular inset image showing a perspective view of server racks in a data center, with blue and yellow lights reflecting off the metal surfaces.

Fewer Data Centers

Less real estate

A circular inset image showing a close-up of a microchip or integrated circuit, with a triangular highlight on its top surface.

More Compute

More tokens/\$\$

A circular inset image showing a green microchip with glowing green points of light, possibly representing energy or efficiency.

Higher Efficiency

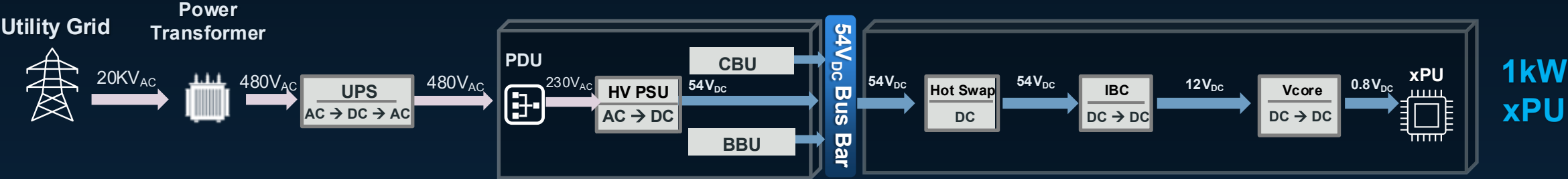
Less water used

xPU Power Increase Drives Move to High Voltage



AC & Low Voltage Distribution and Conversion

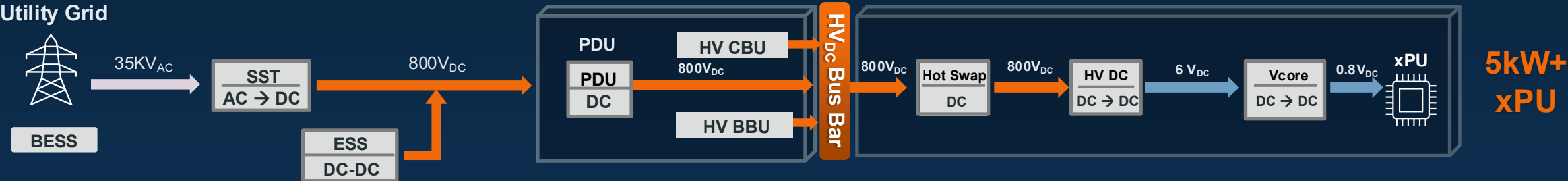
Lateral Vcore



Mechanical Transformer; Low Voltage Storage & Protection

High Voltage DC Distribution and Conversion

Vertical Vcore -VPD

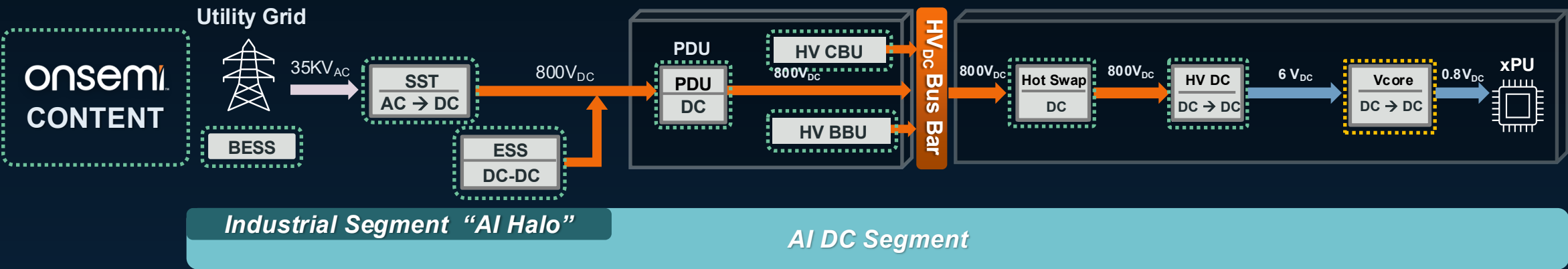


Solid State Transformer; High Voltage Storage & Protection

High Voltage Reaches the Core – Content Multiplies



Grid to Core High Voltage Plays to Our Strength



More Power, Limited Space

More High Voltage Content

More Energy Storage & Load Balancing

Mechanical to Semiconductor Content

More Control, Intelligence, Safety

Multi-technology capabilities required to solve the power density challenge

As Technology Breadth Grows, Competitor Field Shrinks

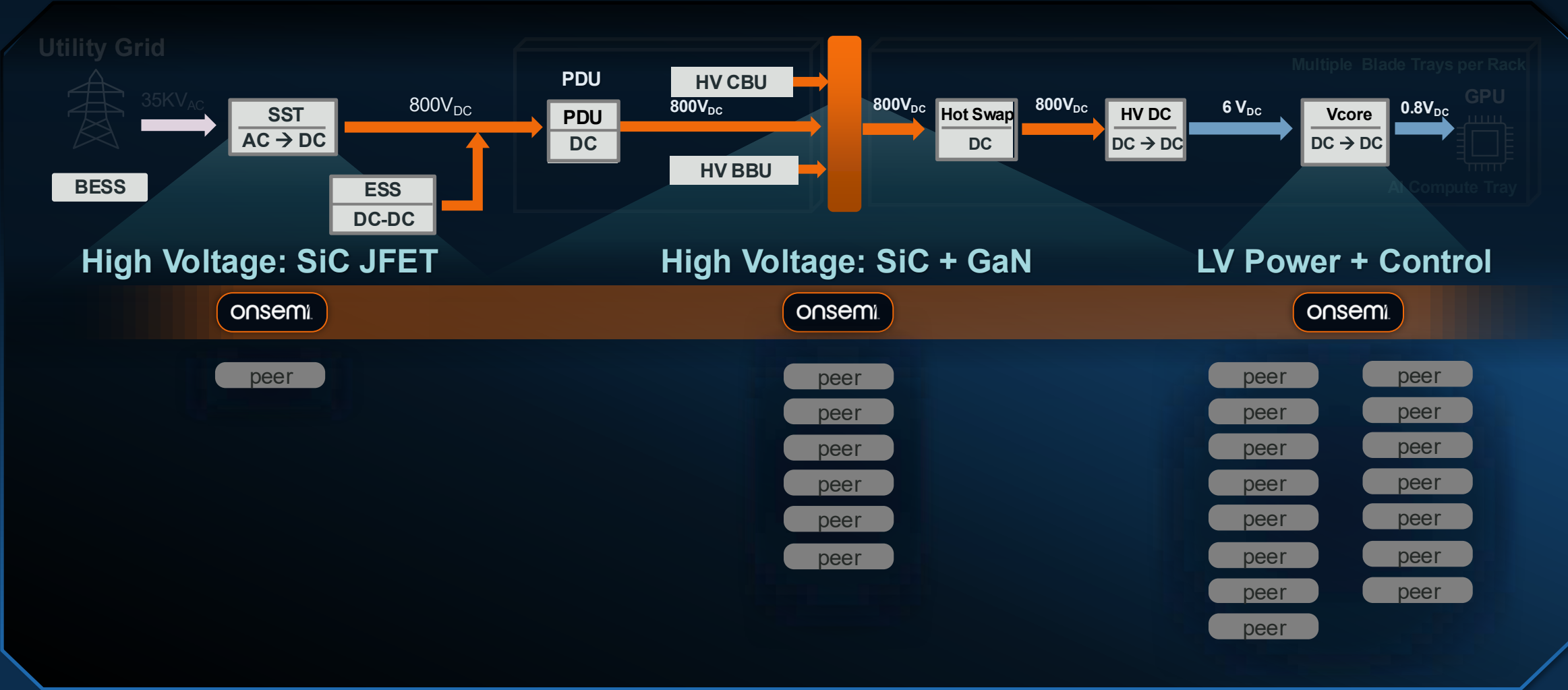


HV

Treo

EPP

Power and Sense Portfolio



Win with Capability Breadth + Technology Differentiation

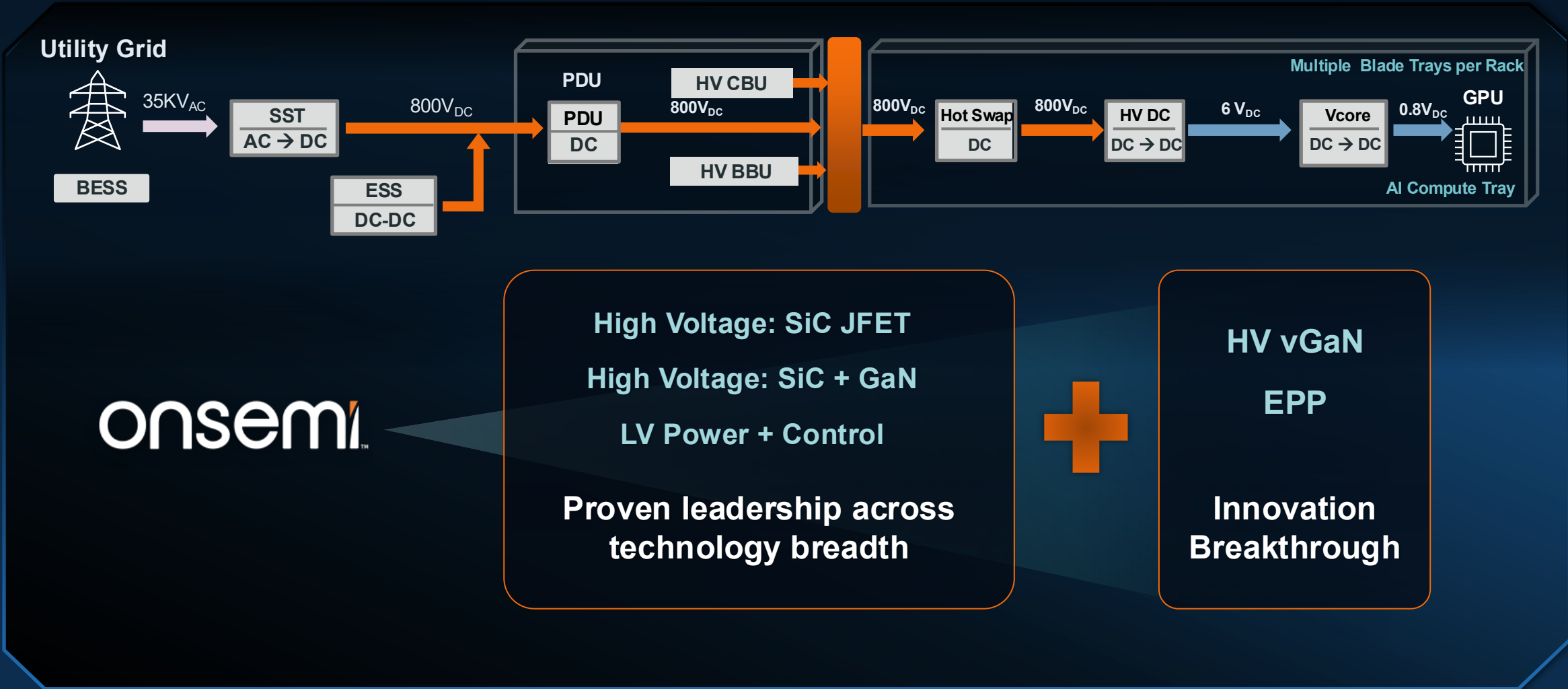


HV

Treo

EPP

Power and Sense Portfolio



vGaN Enables Highest Density 800V → 6V IBC

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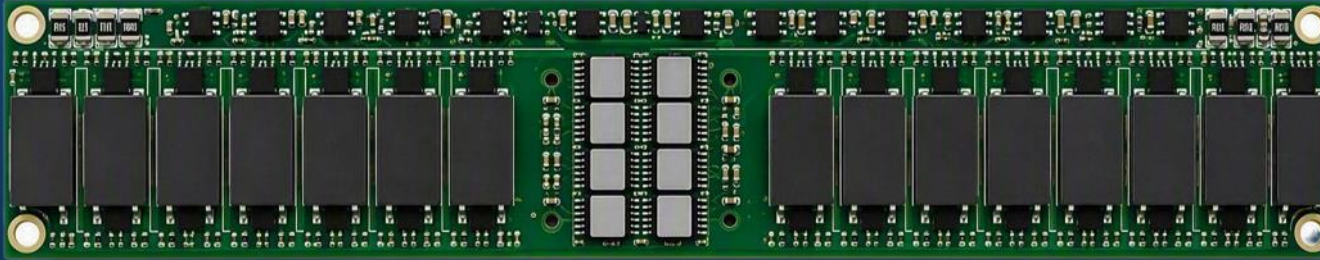
HV

Treo

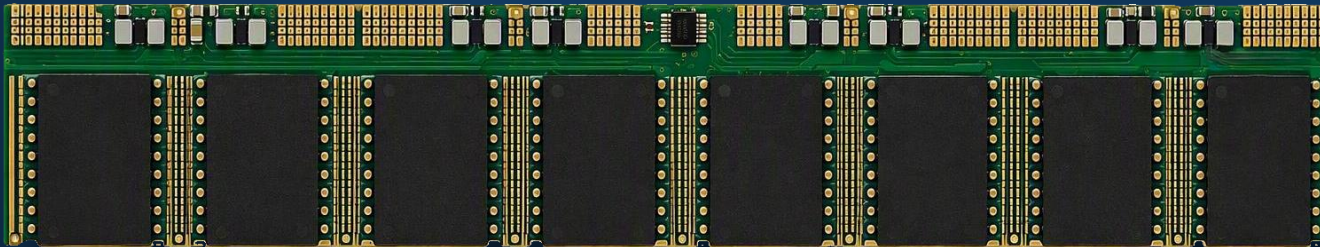
EPP

Power and Sense Portfolio

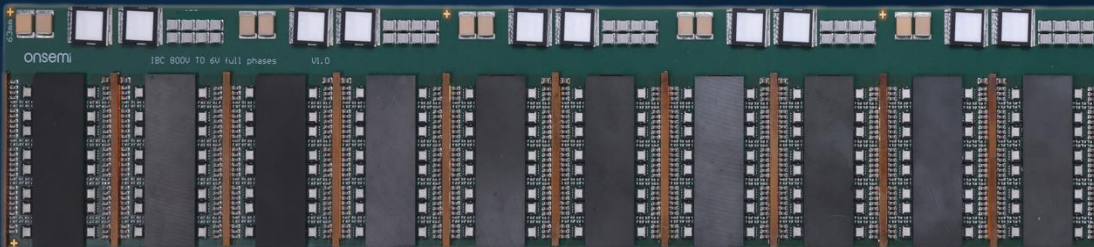
Competitor
1



Competitor
2



onsemi

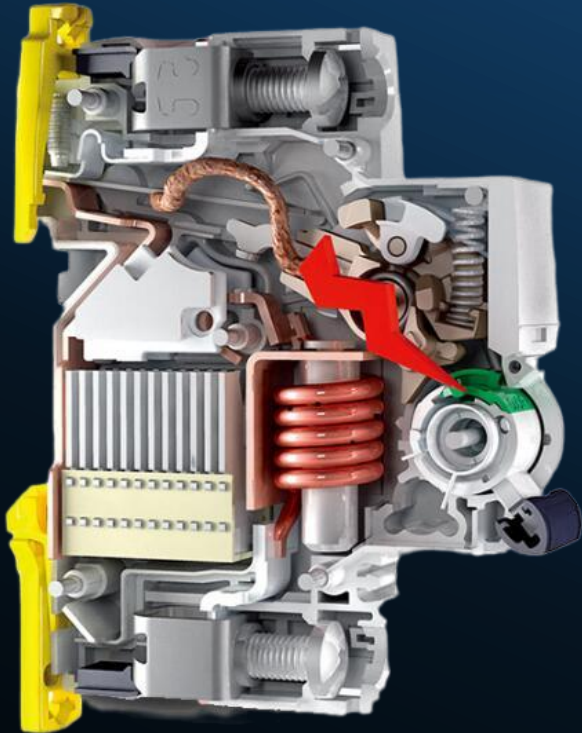


vGaN + Unique magnetics
= 20% smaller size

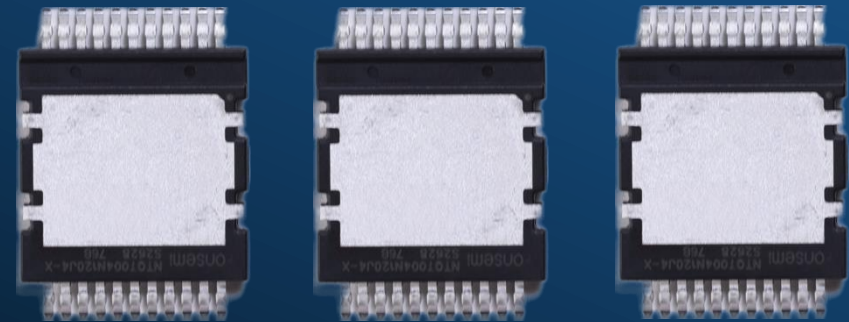
Higher Power density = More compute in Rack = Lower Cost per token

Mechanical to Solid State Fault Protection

onsemi



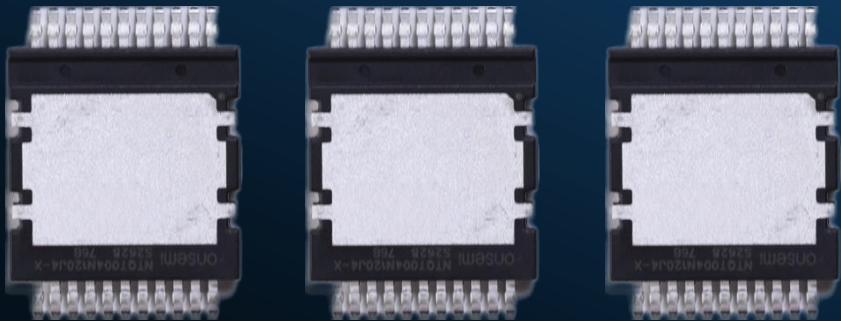
Mechanical Circuit Breaker



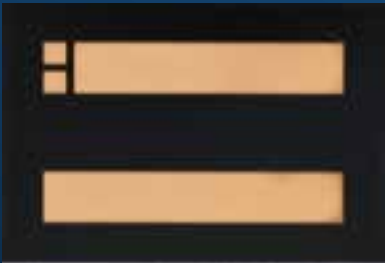
**Industry-Standard
Solid State Circuit Breaker**

High Voltage Architecture needs multiple Fault Protection points

EPP + SiC JFET: Redefining the Density Benchmark



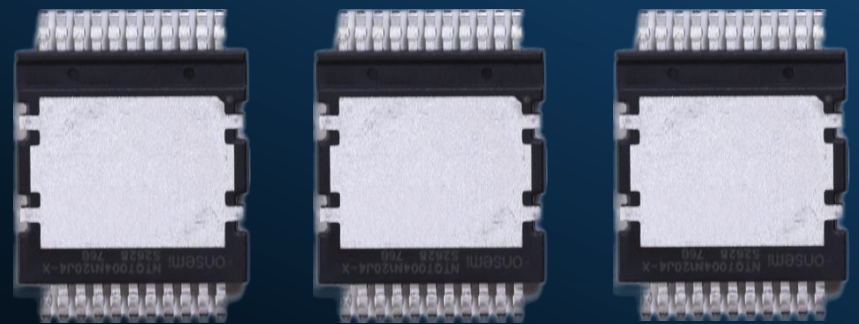
Industry-Standard SSCB



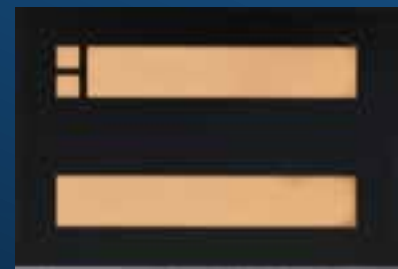
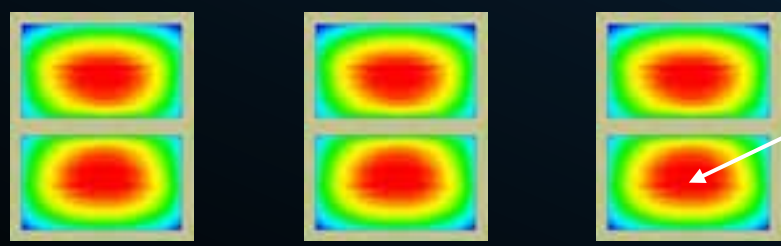
Over 50%
Smaller

EPP SSCB

EPP + SiC JFET: Redefining the Density Benchmark



Industry-Standard SSCB



Over 50%
Smaller

EPP SSCB



20% cooler

Smaller size + Less cooling = Better TCO

EPP Enables Highest Vcore Power Density

onsemi

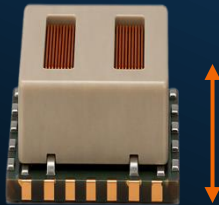
HV

Treo

EPP

Power and Sense Portfolio

2 A/mm^2



Z = 5 mm
with inductor

Available now

Lateral Power Delivery
2-Phase SPS + Inductor

$>3 \text{ A/mm}^2$

SPS in EPP



Z = 2 mm
With inductor

Available 2027

Vertical Power Delivery
onsemi enabled 4-Phase VPD
In partnership with module vendors

EPP enabled SPS

**New Vcore Win
2026**

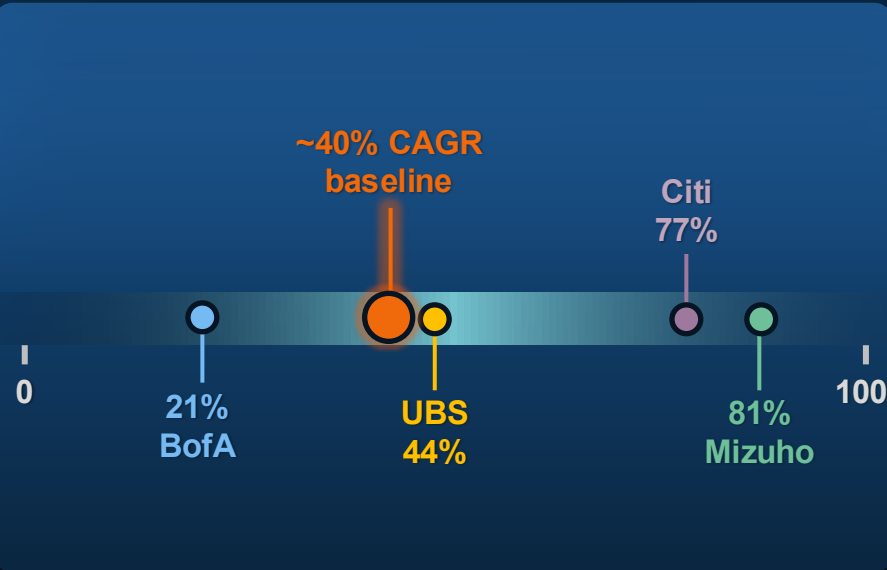
Digital multi-phase control
Unique inductor design

Higher Power Density → Better Customer TCO → Revenue & Margin Growth

onsemi

AI DC TAM CAGR

Growth estimates vary
2026 – 2030



Our technology innovations allow us to significantly outgrow the market

AI DC Revenue

>2X in 2026

2X in 2027

Long-term Growth

+ 10 pts
above market

50%+
revenue CAGR

2026-2030

~5X AI DC Revenue Growth
>\$500M (2026) → >\$2.5B (2030)



AI turns power into **one**
connected system.

The prize grows
The field shrinks

onsemi™

Solves the
toughest
challenges



Expanding the Core: Automotive and Industrial

Sudhir Gopalswamy

Group President, Analog & Mixed-Signal and Intelligent Sensing Groups

Expanding the Core

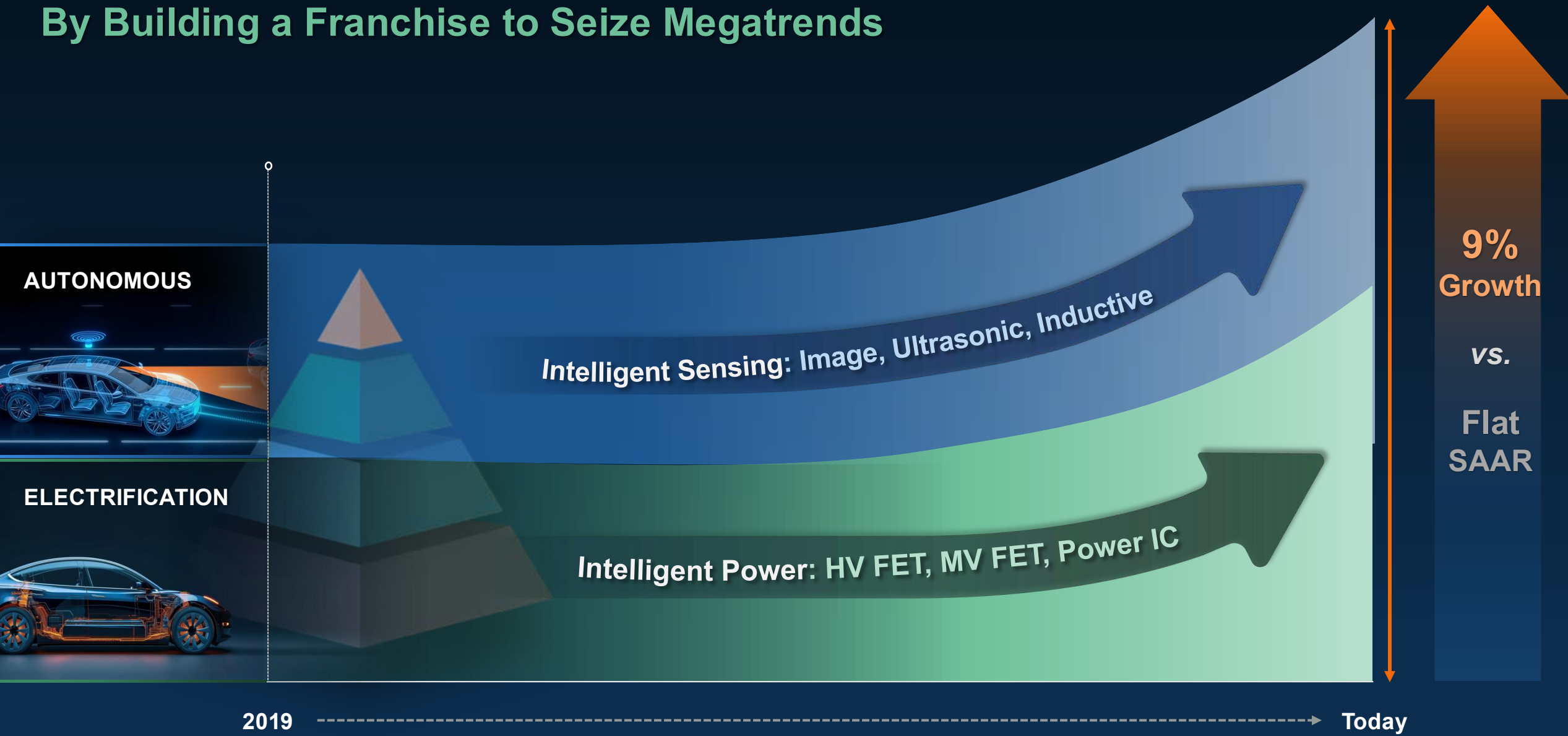
Automotive

Industrial

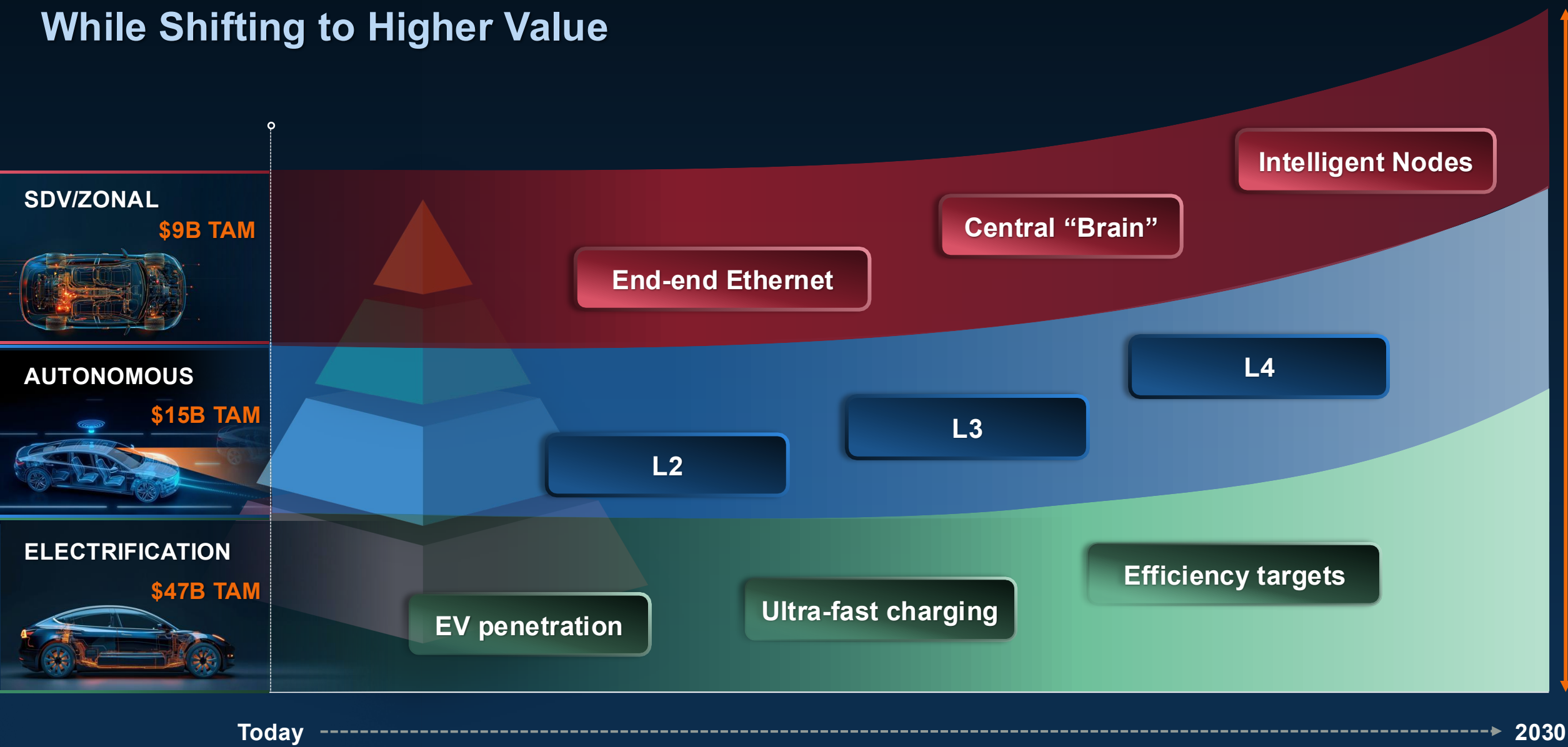
We Have Outgrown Automotive SAAR by 9%

By Building a Franchise to Seize Megatrends

onsemi



We Will Continue to Outperform SAAR by 9% While Shifting to Higher Value

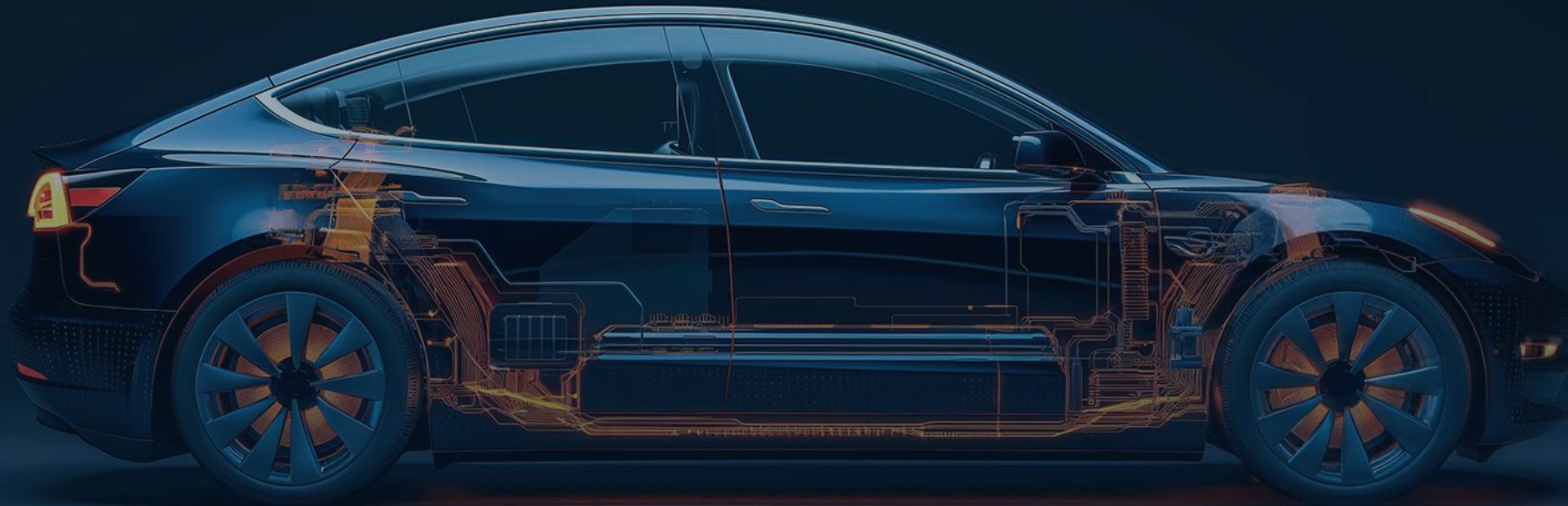


Intelligent Power Growth Plan

**Extend SiC Technology
Leadership**

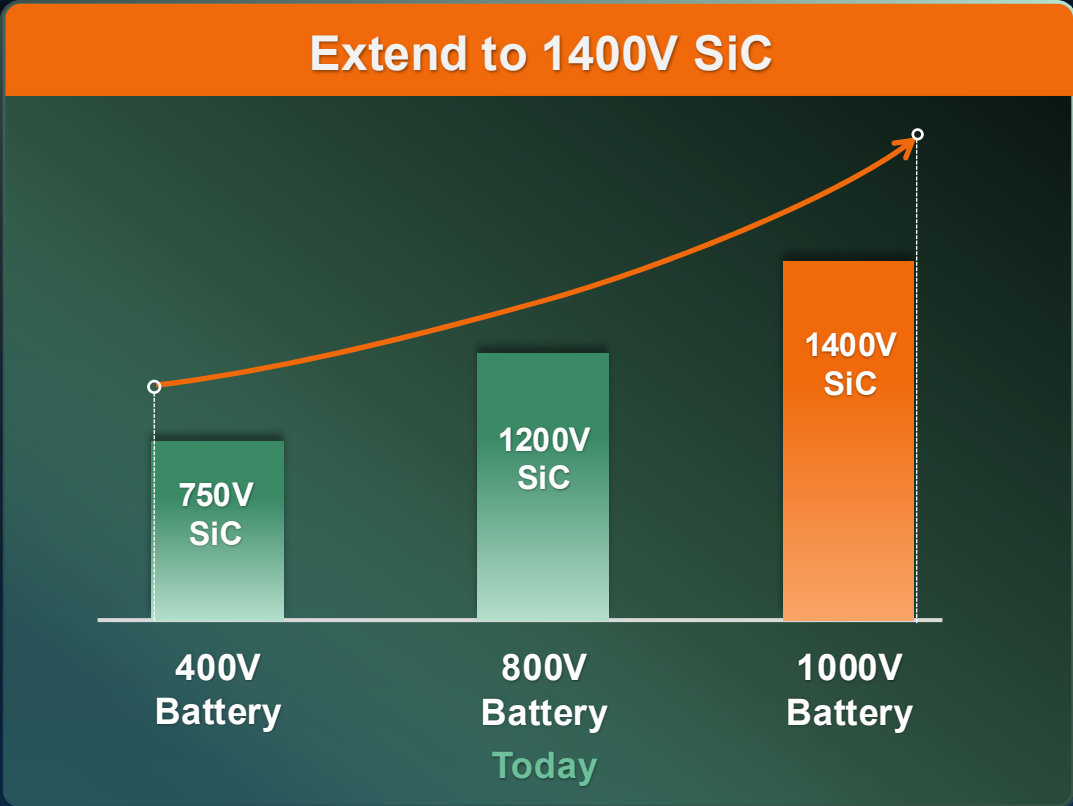
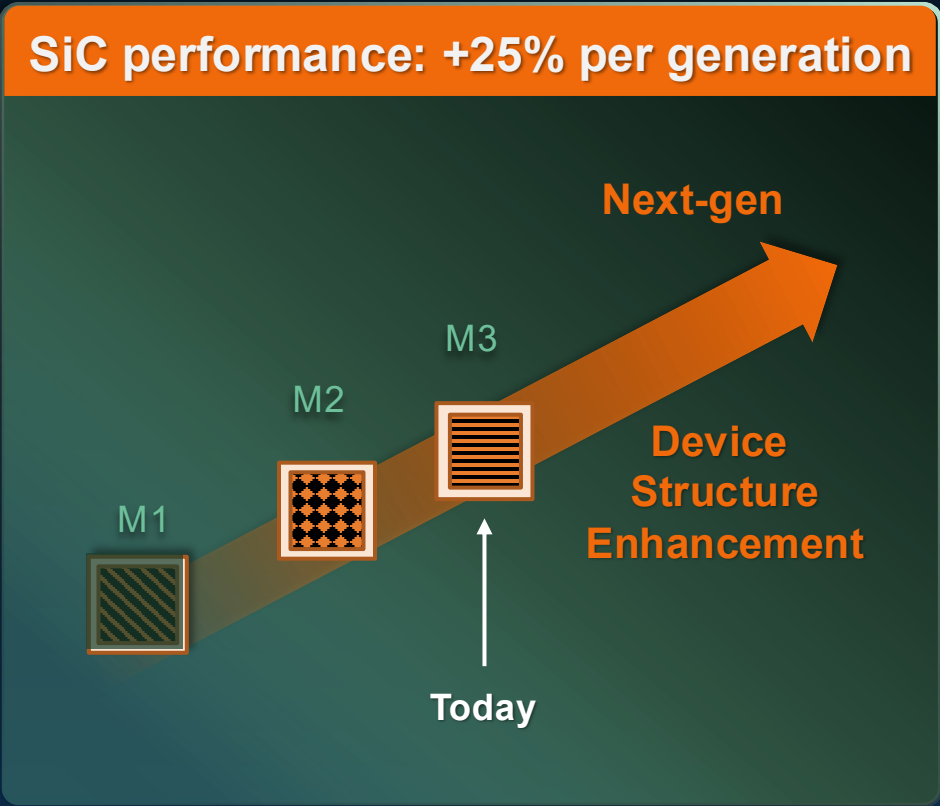
**Expand System Value
with Treo Power ICs**

**Change the Game with
EPP**



SiC Leadership Provides Growth Foundation

We Will Continue to Raise the Bar



ELECTRIFICATION
\$47B TAM



Customer
Value

Efficiency → Range or System Cost
Power Density → Horsepower or System Cost
Higher Voltage → Faster Charging

Expand System Value: Treo Power ICs

Power Tree



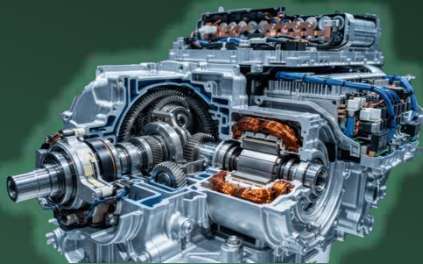
Power
Protection

Power Tree



LDOs

Traction & OBC



Current
Controllers

Front/Rear Lighting



LED Drivers

“Brain”



SPS, DC-DC
Controllers

Enabled by Treo

Intelligent Treo SiC Current Controller

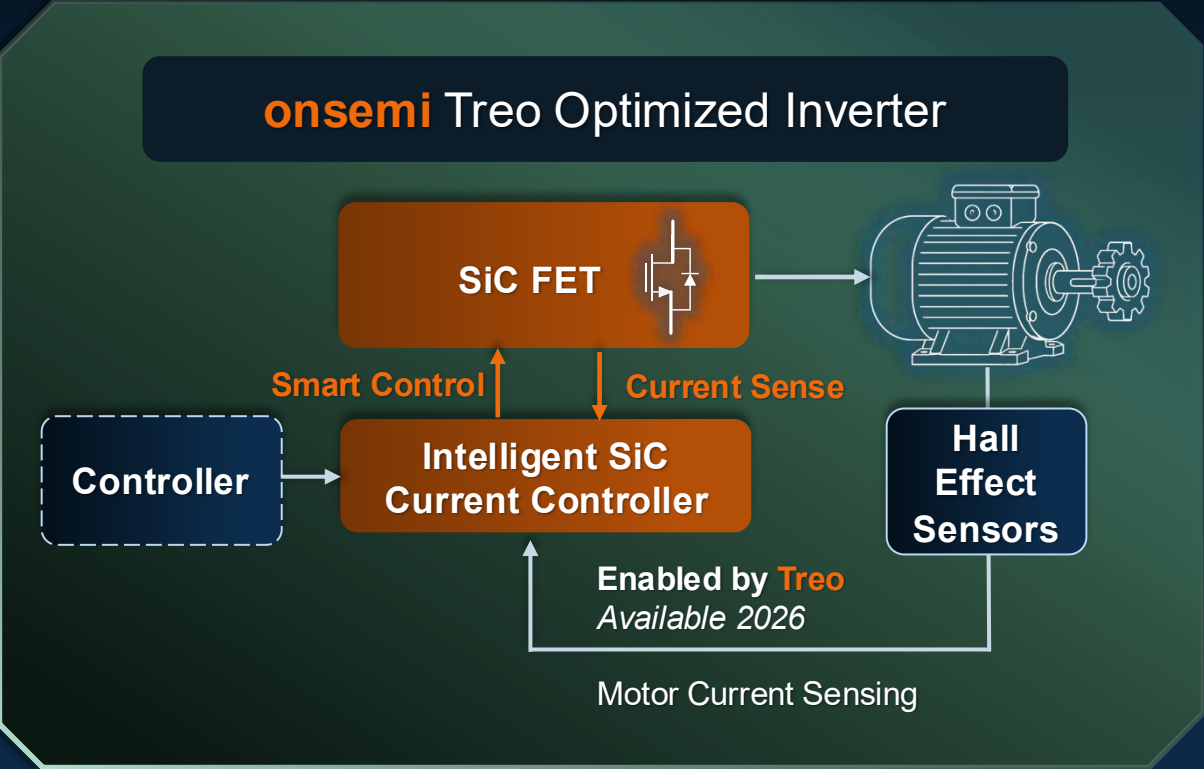
onsemi

HV

Treo

EPP

Power and Sense Portfolio



1-Gen

SiC Boost

5%

BOM Savings

ELECTRIFICATION
\$47B TAM



Customer Value

Efficiency → Range or System Cost

Power Density → Horsepower or System Cost

Integration → System Cost

EPP Transforms Inverter Solutions

onsemi

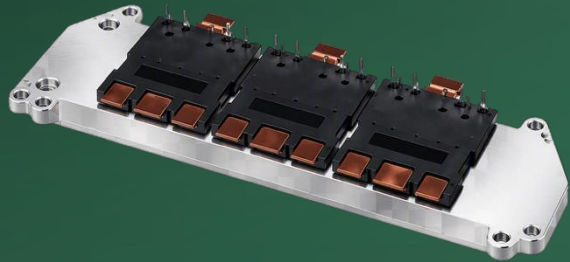
HV

Treo

EPP

Power and Sense Portfolio

State-of-the-art



EPP



Available 2026

4x
Power
Density

High end
**1 Inverter
Platform**
Low end

15%
Power
Losses

ELECTRIFICATION
\$47B TAM



Customer Value

Power Density → Smaller, Lighter → Flexibility
Scalability → Lower R&D & Manufacturing Cost
Efficiency → Range or System Cost
Full System → Fast Time-to-Market

Intelligent Sensing Growth Plan

Capitalize on Sensor Proliferation

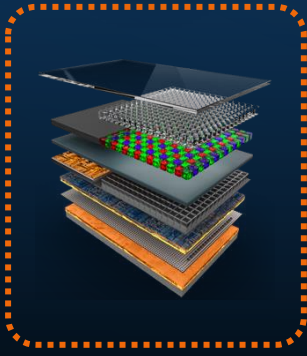
Extend Sensing Performance Leadership with Treo

Enhance Vision with New Image Sensing Modalities



Broadest Range of Sensing Solutions

AUTONOMOUS
\$15B TAM



Image

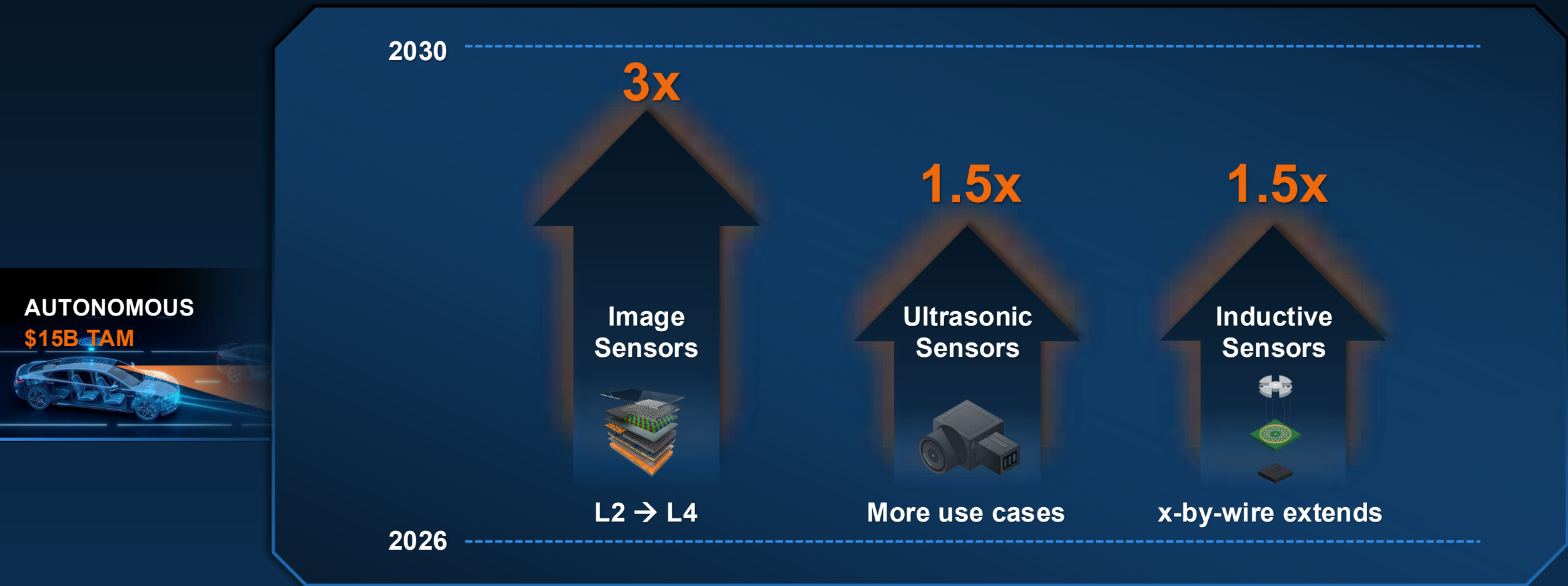


Ultrasonic



Inductive

Sensors Proliferate As Autonomy Scales

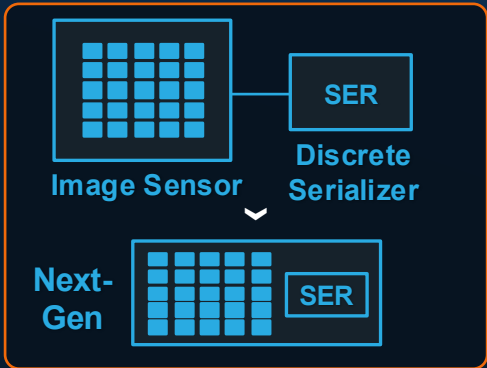


Raising the Bar on Intelligent Sensing

AUTONOMOUS
\$15B TAM



Image Sensing



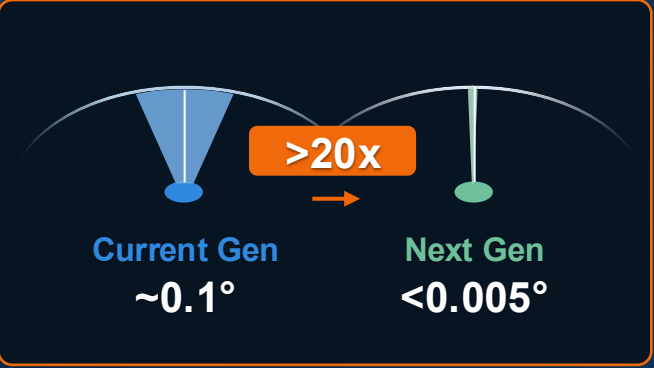
Available 2027

Ultrasonic Sensing



Available 2027

Inductive Sensing



Available 2027

Enabled by Treo



Customer Value

Accuracy → Safety & Reliability
Integration → System Cost

Enhancing Vision for the Next Phase of Perception



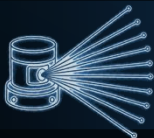
PERCEPTION STACK



Vision



Radar



Lidar

CHALLENGES

Adverse weather conditions

Spatial resolution

System cost

AUTONOMOUS
\$15B TAM



Superhuman Vision



SWIR

See through fog and rain

Industrial available today, Auto in Advanced R&D



iToF

High-res depth at <15M
Detect hazard at 100M

Industrial available today, Auto in Proof-of-concept



Vision

Capture detail in any light

HDR available today

Customer Value

Enhanced Vision → Safety

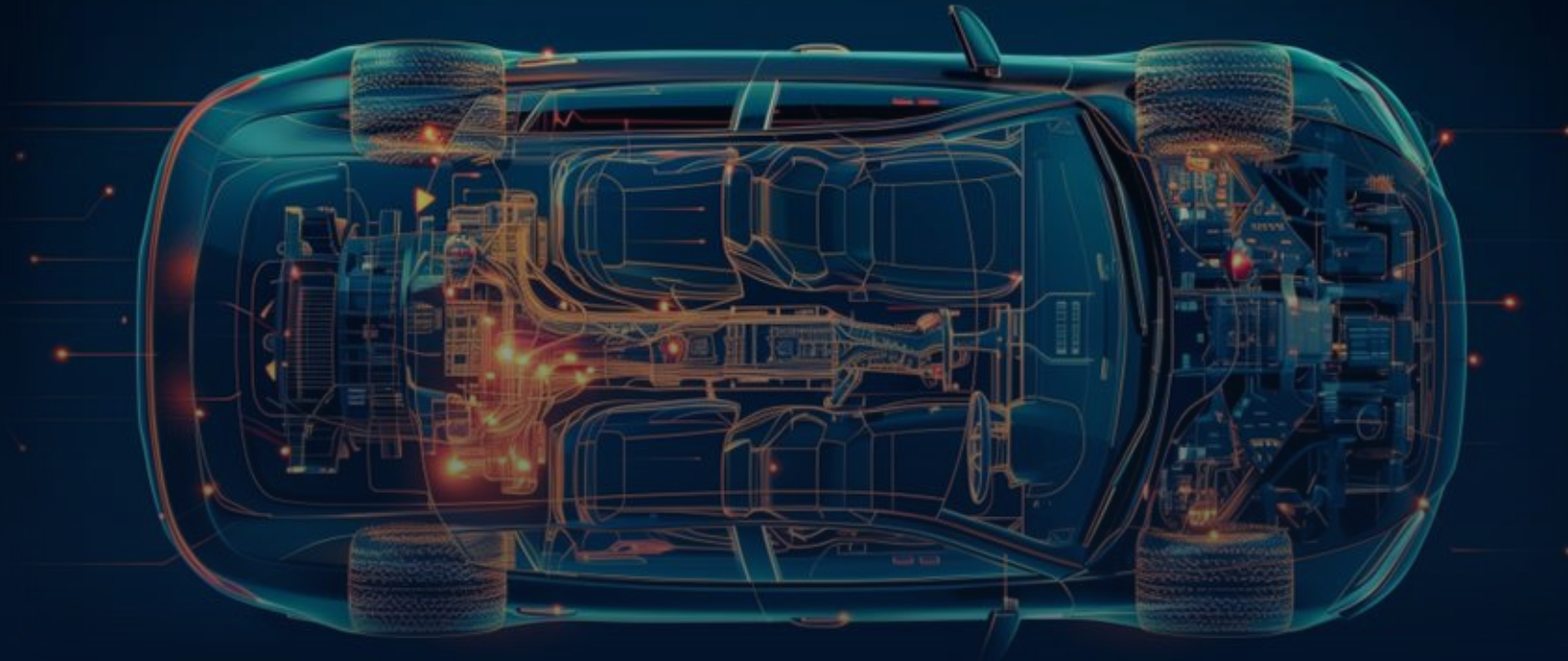
iToF → System Cost

AUTONOMOUS
\$15B TAM



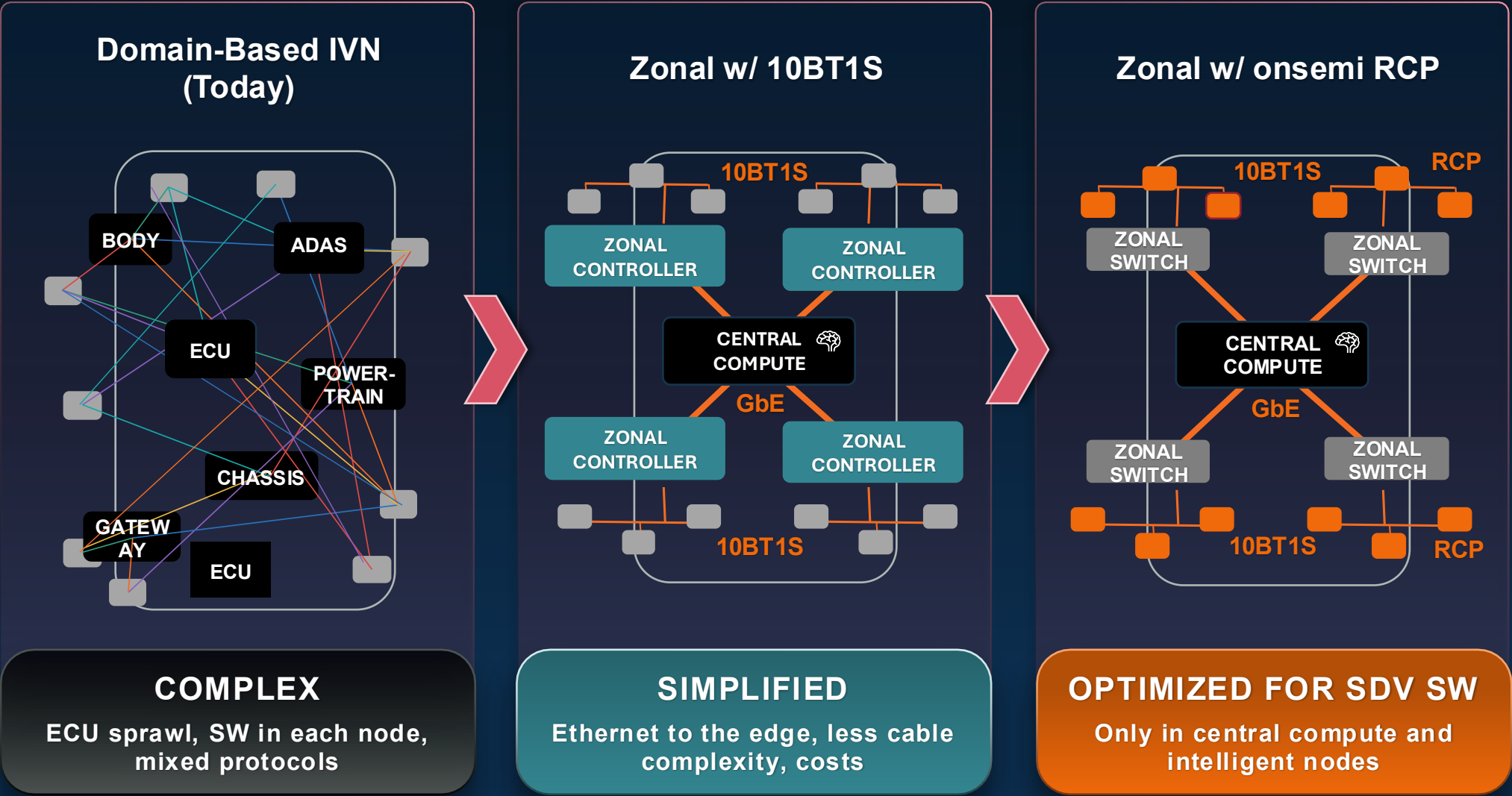
New Growth Driver: Software Defined Vehicle/Zonal

Expand Content and Intelligence at the Nodes



New Growth Driver: SDV/Zonal

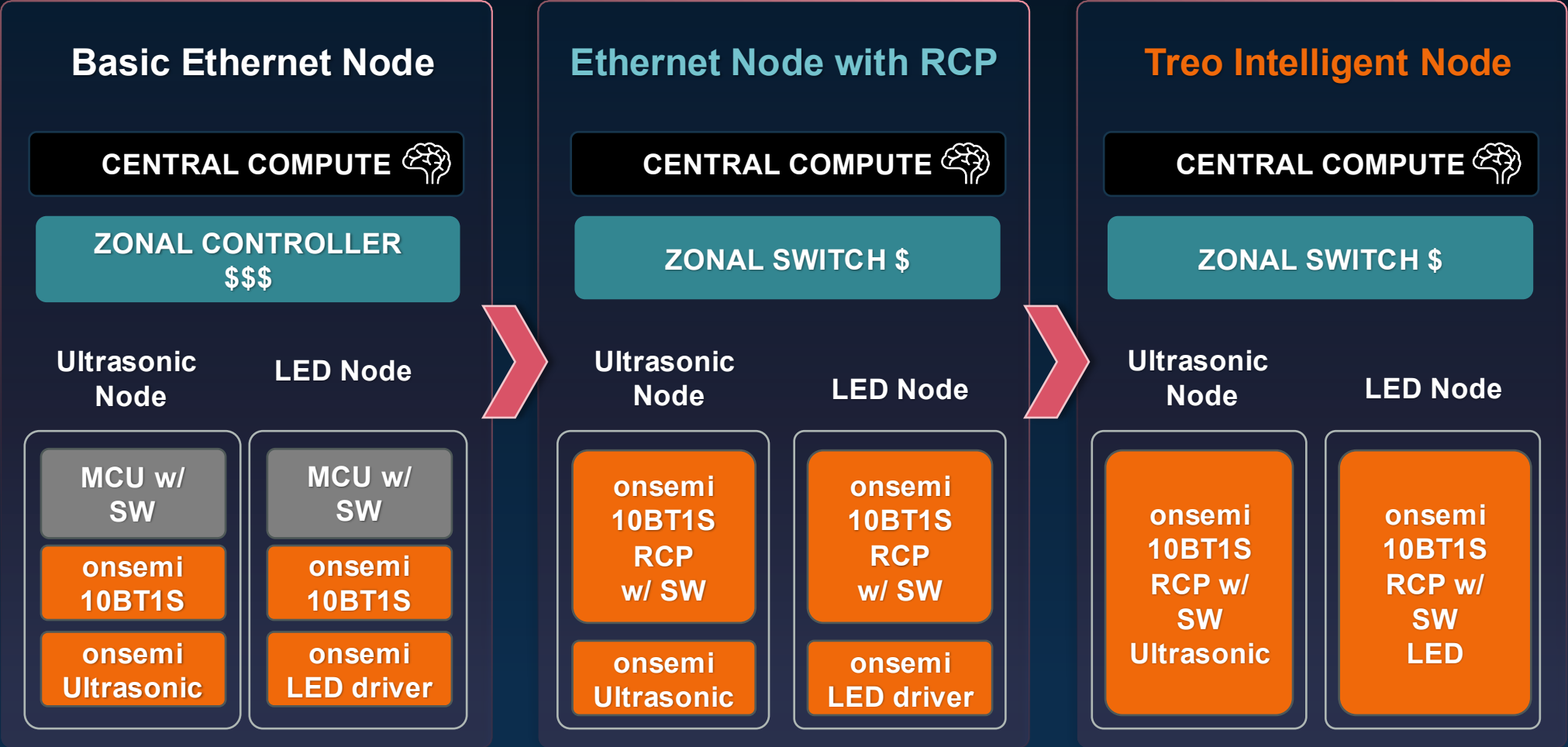
SDV/ZONAL
\$9B TAM



New Growth Driver: SDV/Zonal



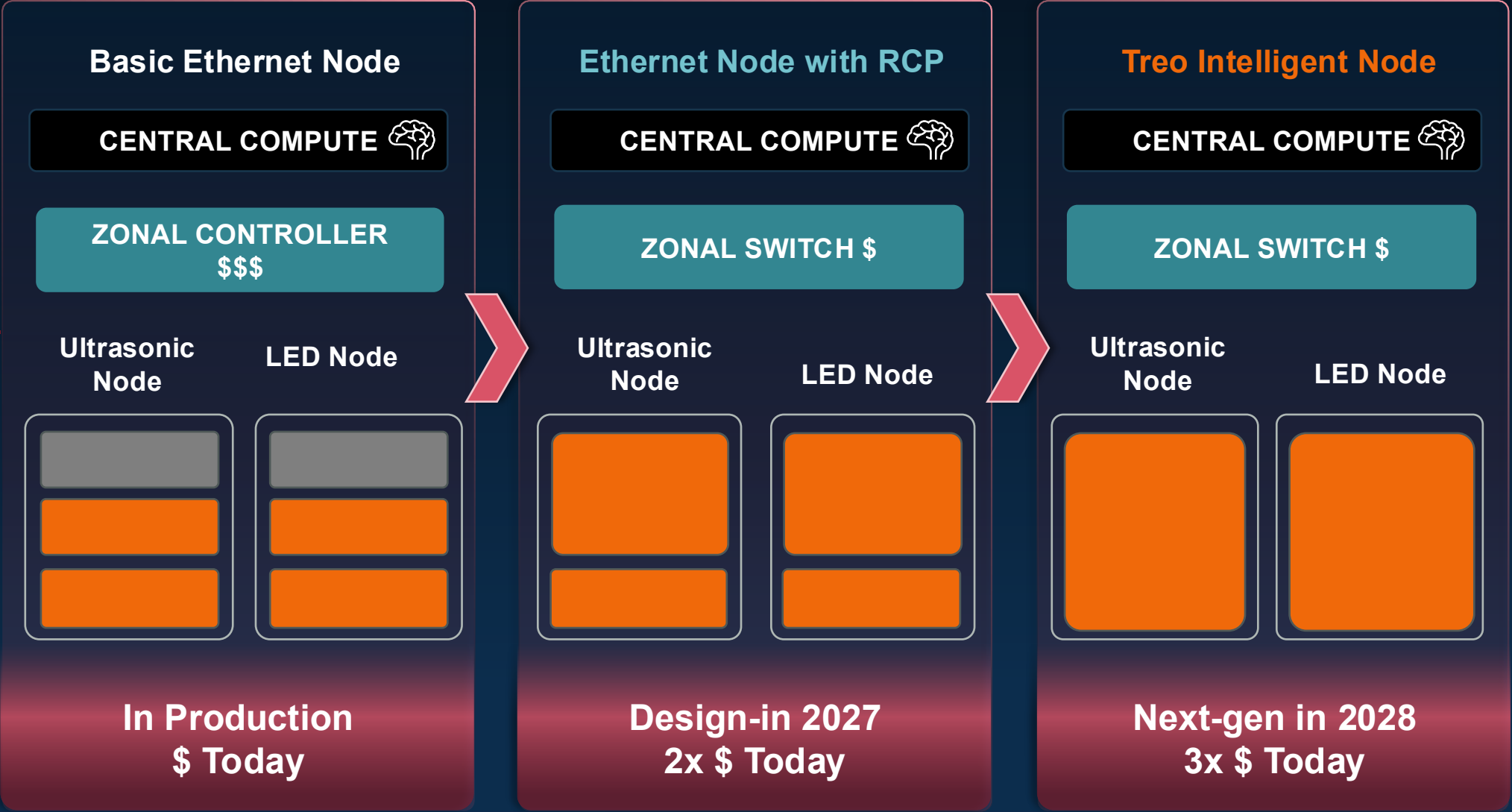
SDV/ZONAL
\$9B TAM



onsemi VALUE

Leading the SDV Evolution

SDV/ZONAL
\$9B TAM



Building the Car: onsemi in Every Subsystem

onsemi

Vehicle Electrification xEV

HEV / PHEV / BEV

- **EPP**
- EliteSiC FET
- **SiC Current Controller**

48V Transition

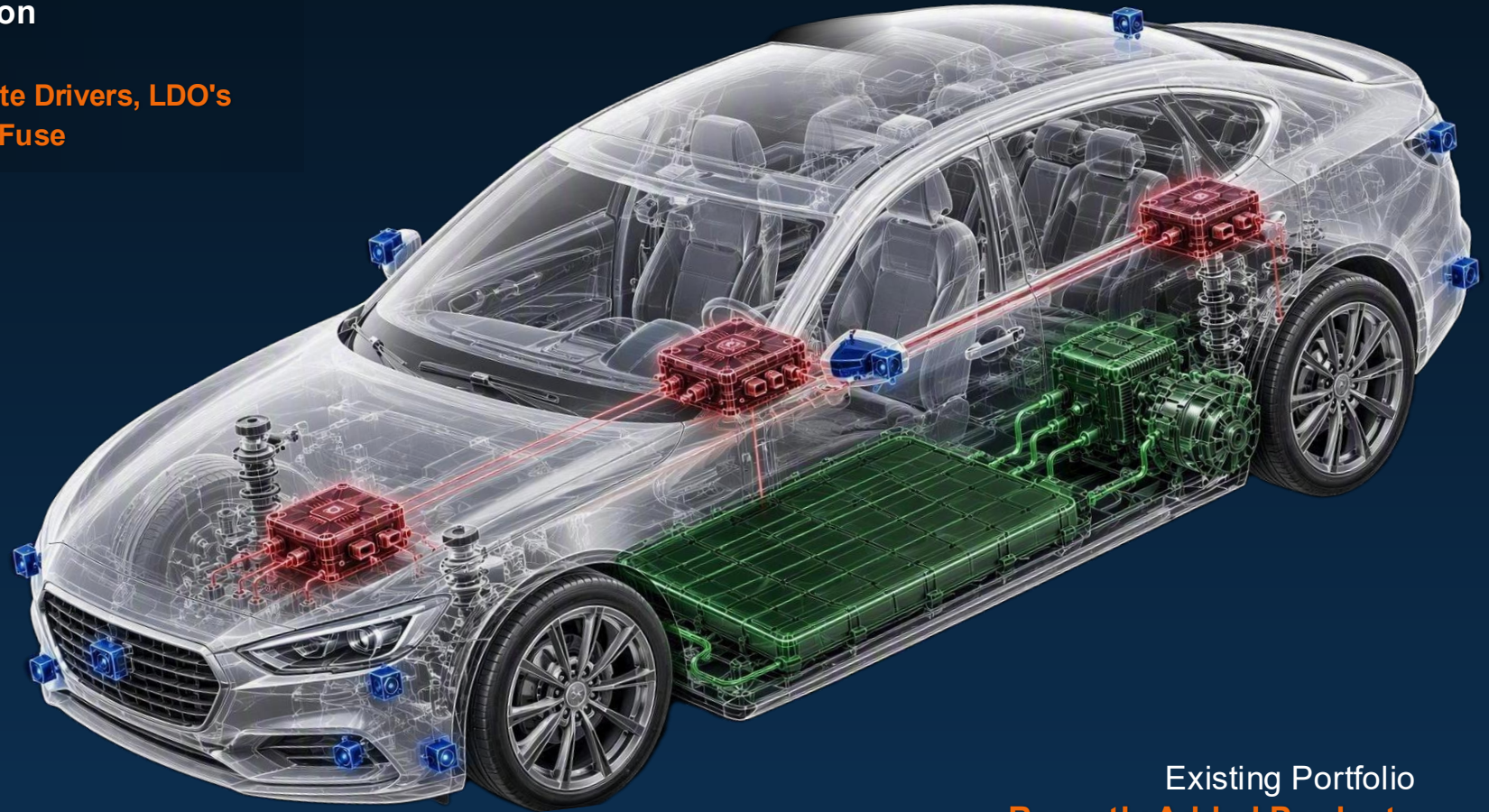
- HV Si FET
- **GaN/SiC Gate Drivers, LDO's**
- **SmartFET/eFuse**

Zonal Electronics

- Auto LED Drivers
- **SmartFET/eFuse**
- **10BASE-T1S Ethernet**
- CAN/LIN
- Standard Products (LDOs, Amps)
- Small Signal Protection

ADAS and Autonomous Driving Solutions

- 8Mp, 3Mp image sensor
- **iToF**
- **SWIR**
- Ultrasonic Sensing
- Inductive Sensing
- Rain & Light Sensing



Existing Portfolio
Recently Added Products

Up to \$2000 of onsemi content per vehicle

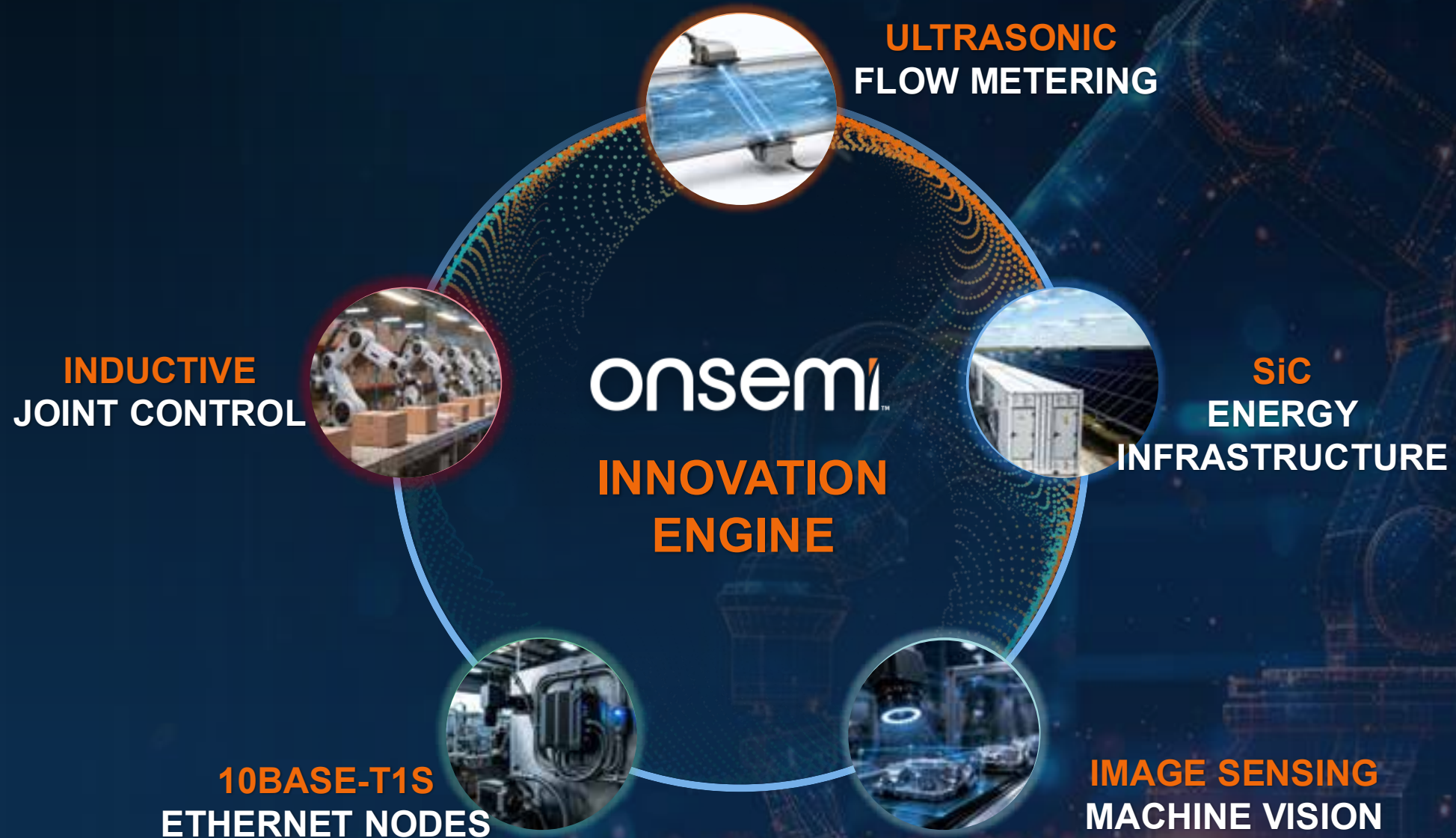
Automotive Innovations...

onsemi



Automotive Innovations... Enable Growth in Industrial...

onsemi



...and Lead to the Next Major Growth Opportunity

onsemi

The Era of Physical AI

SENSE

Perception of the physical world

POWER

Efficient power conversion

CONTROL

Precise actuation and control

The Era of Physical AI has Already Begun

onsemi

Autonomous machines that sense, decide, act and adapt



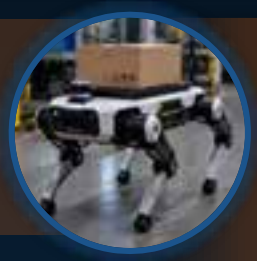
The Evolution to Humanoids Yields Content Expansion

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Warehouse
AMRs

+ Autonomy, Legs



Legged
AMR



Factory Arms

*+ Gripper Hands,
Force Sensing*



Dexterous
Hands



Autonomous
Cars

*+ Multi-modal VLA,
Reasoning*



“Reasoning”
Vehicles

Physical AI:
\$6B
TAM by 2030



Building the Humanoid: **onsemi** in Every Subsystem

onsemi

Vision Systems

- Image sensors
- **iToF sensors**
- **SWIR**
- DC-DC/LDOs

30+ Limb Actuators

- **6x GaN FET**
- **3x GaN Driver**
- **Inductive sensors**
- **10BASE-T1S**
- **Intelligent Control**
- Current sensors
- UVP/OVP

15+ Hand Actuators

- MOSFET/**GaN**
- Gate Drivers
- **Intelligent Control**
- **10BASE-T1S**

HEAD/PERCEPTION

NECK

SHOULDERS

UPPER ARMS

ELBOWS

HANDS

LEGS

ANKLES/FEET

TORSO/COMPUTE

POWER SYSTEM

CORE SENSORS

WAIST/HIPS

BATTERY

KNEES

COMMUNICATION

Power Tree

- **eFuse**
- SiC/MOSFET
- DC-DC/LDOs

Sensors

- Ultrasonic sensors
- Pressure/force
- Audio DSP
- **Sensor Hub MCU**
- Temp monitor

Connectivity

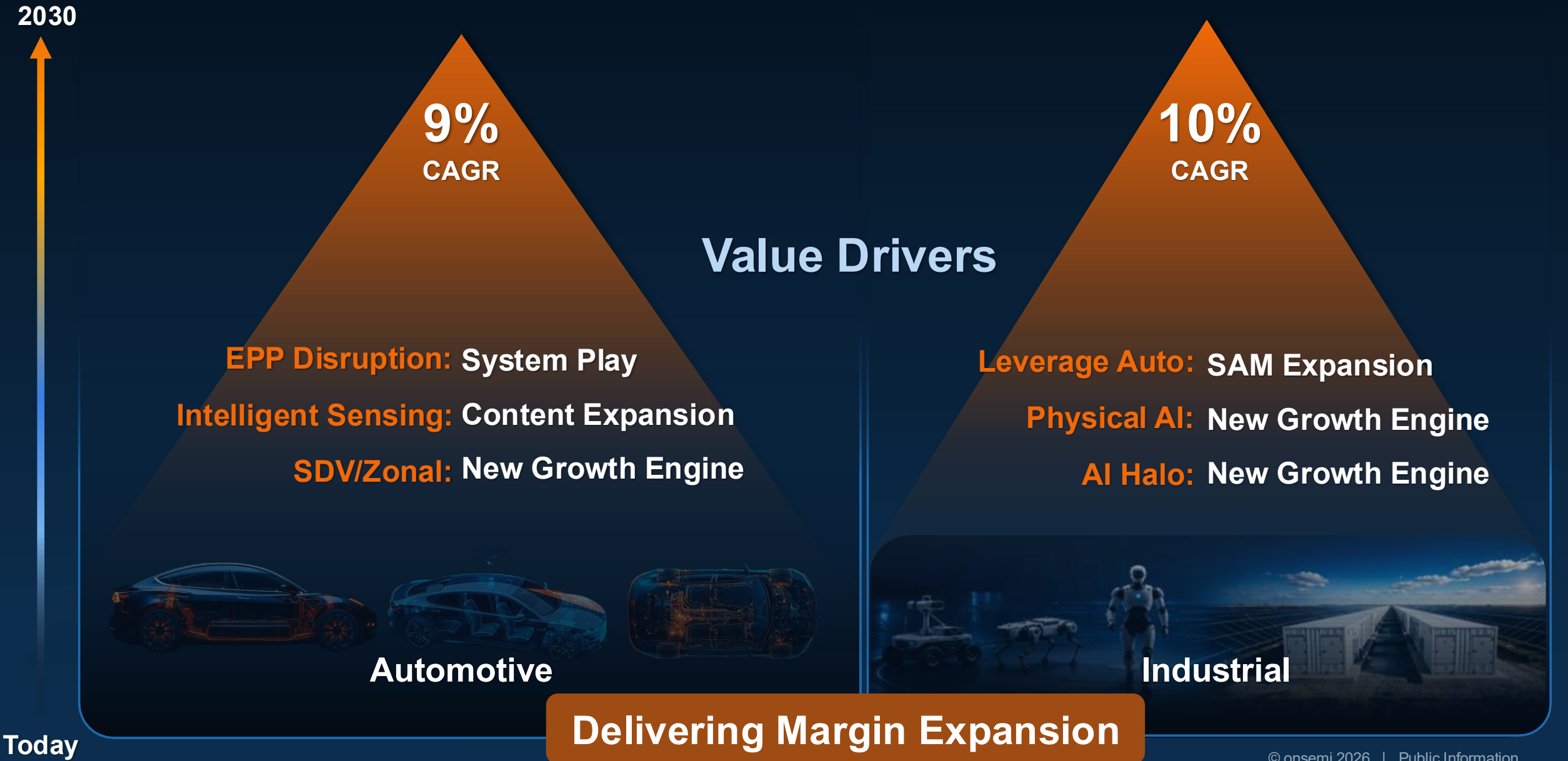
- **10BASE-T1S**
- CAN/LIN
- BLE

Existing Portfolio

Recently Added Products

Up to \$900 of onsemi content per humanoid

Expanding the Core: Automotive and Industrial





Turning Technology Leadership into Durable Financial Performance

Thad Trent

Executive Vice President and CFO

Market Inflection. Differentiated Capabilities. Shareholder Value Creation.

The onsemi logo is centered within a glowing blue circuit board graphic that radiates outwards, connecting to various industry images like a car, a factory, a satellite, a hospital, and a drone.

HIGH-VALUE, SECULAR MARKETS

AI Data Center, Automotive, Industrial

DIFFERENTIATED CAPABILITIES

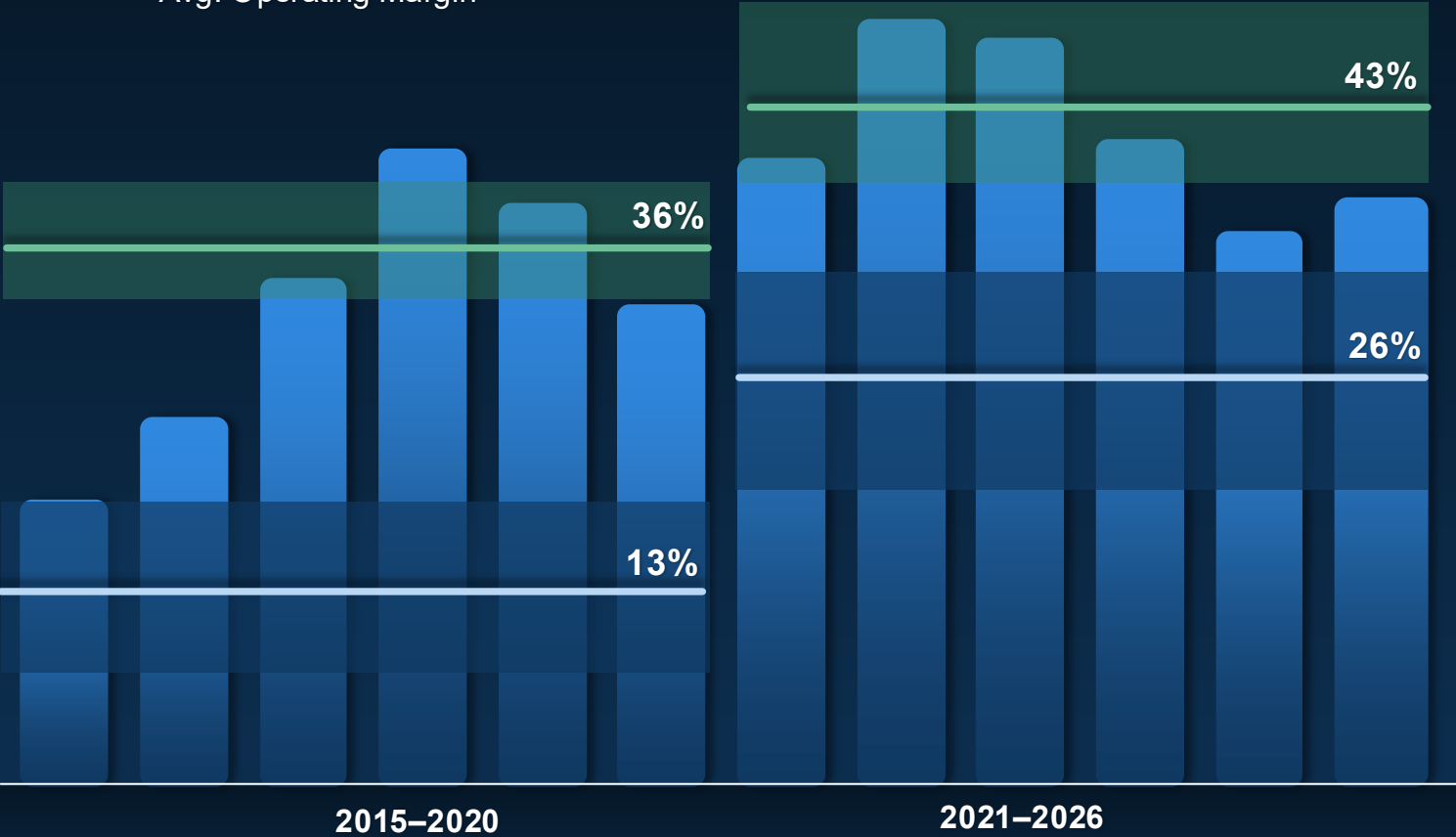
Differentiated technology expands margins

The Power of onsemi's Transformation



Non-GAAP

- Revenue
- Avg. Gross Margin
- Avg. Operating Margin



*BANDS REPRESENT HIGH AND LOW OF EACH METRIC DURING THAT PERIOD

Structural step function margin improvement

- Differentiated products, Fab Right, portfolio rationalization – completed exits of ~\$900M annualized

Higher Operating leverage

- Improved cost structure, OpEx efficiency (Rev/employee increased ~2X)

Proven downside resilience

- Sustainable and predictable results

The **Power** of onsemi's Transformation

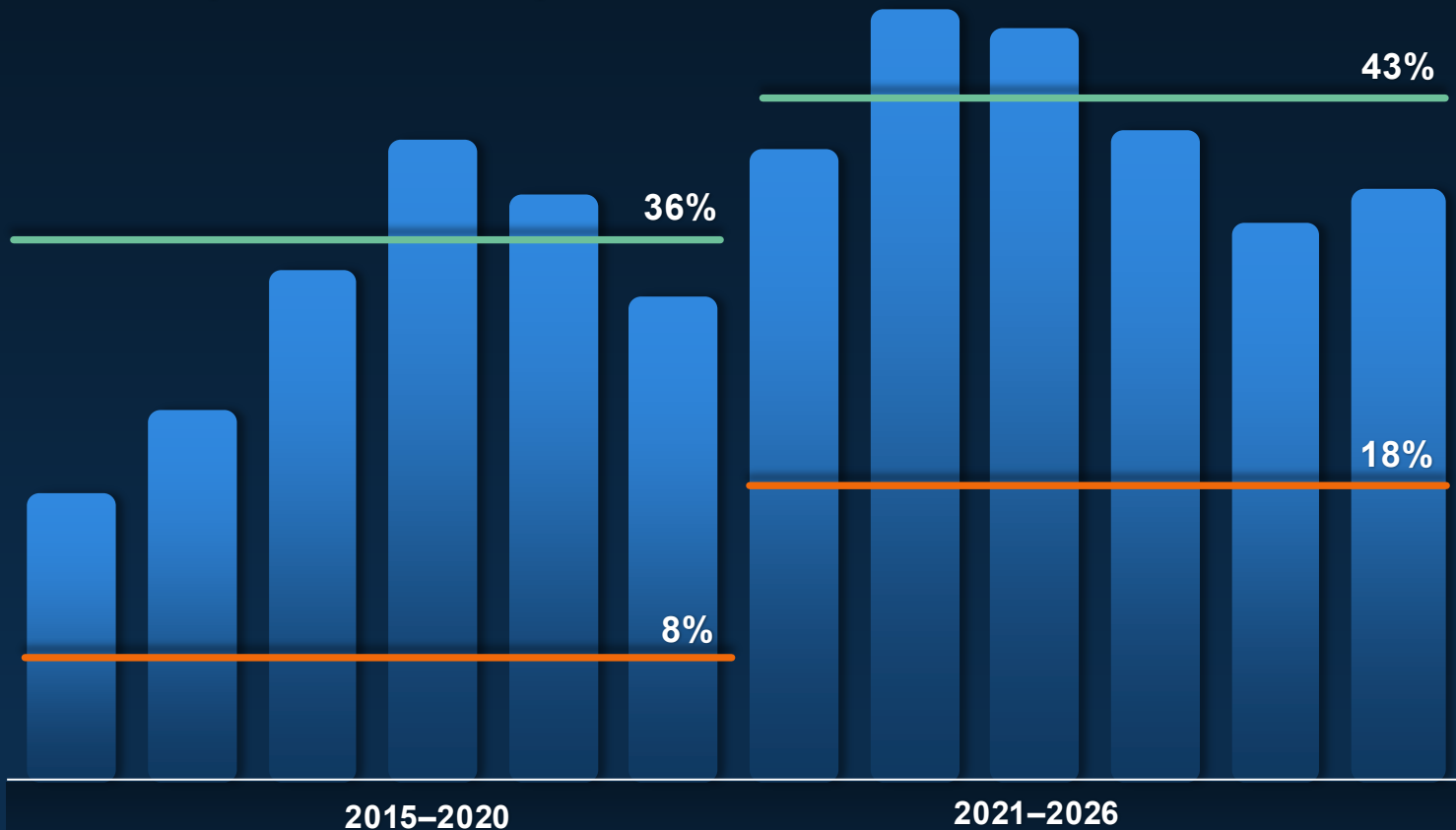
Non-GAAP

onsemi

Revenue

Avg. Gross Margin

Avg. Free Cash Flow Margin



Structural step function margin improvement

- Differentiated products, Fab Right, portfolio rationalization – completed exits of ~\$900M annualized

Higher Operating leverage

- Improved cost structure, OpEx efficiency (Rev/employee increased ~2X)

Proven downside resilience

- Sustainable and predictable results

Strong Free Cash Flow Generation

- Transform from Manufacturing Co. to a Product Co.
- Brownfield capacity expansion

Strategic Investments Drive Significant TAM Expansion

2021-2026

Total Investment: \$8.7B

R&D
Organic Investments
\$3.6B

M&A
Capability Expansion
\$0.8B

CapEx
Capacity Expansion
\$4.3B

- Treo Platform
- Low/Medium/High Voltage
- EPP
- Sensing, 8MP, Ultrasonic
- Core Portfolio Expansion
- SiC JFET
- Vcore
- GTAT
- SWIR Vision
- Vertical GaN
- EFK Expansion
- SiC / vGaN Capacity
- Maintenance

Auto

Power Distribution & Traction
ADAS & Sensing
Zonal architecture

+\$20B TAM

Industrial

Factory Automation & Robotics
Energy & AI Infrastructure
Medical & AD&S

+\$16B TAM

AI Data Center

Low voltage power to xPU
800V to 6V step down (IBC)
Power @ high voltage (ex. rack)

+\$45B TAM

Other

Opportunistic expansion leveraging strategic investments

**\$8.7B investment delivers
\$81B TAM Expansion**

Enabling Innovation Across a Global Customer Base

onsemi

Highly diversified customer footprint spanning 9,000+ customers globally

AUTOMOTIVE

 **BorgWarner** **SCHAEFFLER**

  **HYUNDAI-KIA MOTORS**  **GEELY**

 **AUMOVIO**  **MAGNA**
 **STELLANTIS**

 **XPENG**  **Li Auto**

 **BOSCH Automotive**  **NIO** • **A P T I V** •

 **TESLA**  **Valeo**  **SUBARU**

INDUSTRIAL

 **ABB**  **ZEBRA**  **Schneider Electric** 

 **FUJITSU** **SUNGROW** **simbe**

SIEMENS  **Starkey** **PHILIPS**

Honeywell  **amazon** **Boston Scientific**

 **Veritiv**  **SINENG**  **BOSCH**

 **EAT•N** **dexcom** **Raytheon**

 **TESLA** **SPACEX**  **爱士惟 AISWEI**

 **TELEDYNE TECHNOLOGIES**  **GRID BLOCK** 

AI DATA CENTER

 **Microsoft**  **NVIDIA**

LITEON **Google** **DELL**

flex  **amazon** **EAT•N**

MEGMEET  **Schneider Electric** **intel**

 **AMD**  **Veritiv**  **HERON**

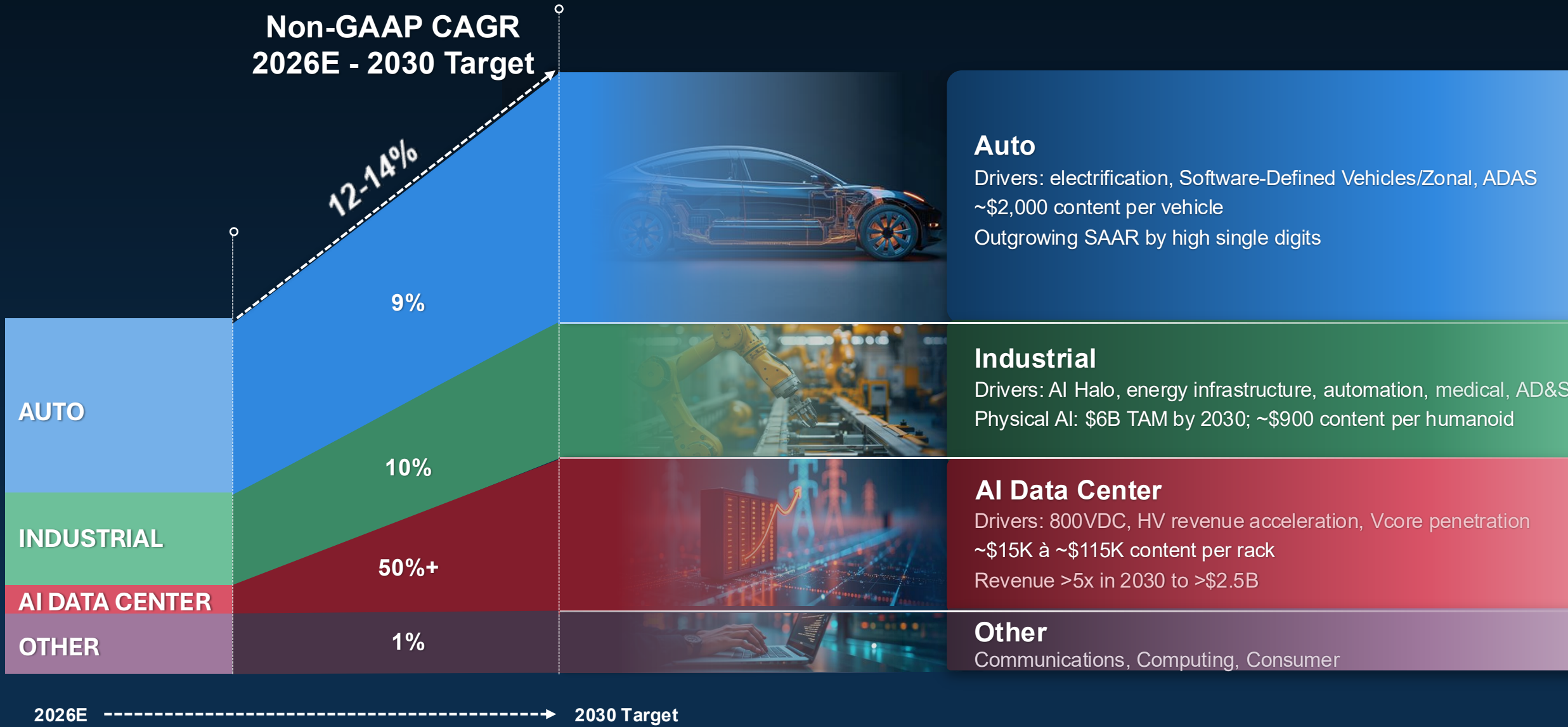
 **Meta**  **Great Wall**  **GRID BLOCK**  **DELTA**

Deep strategic engagements addressing customers' most complex engineering challenges

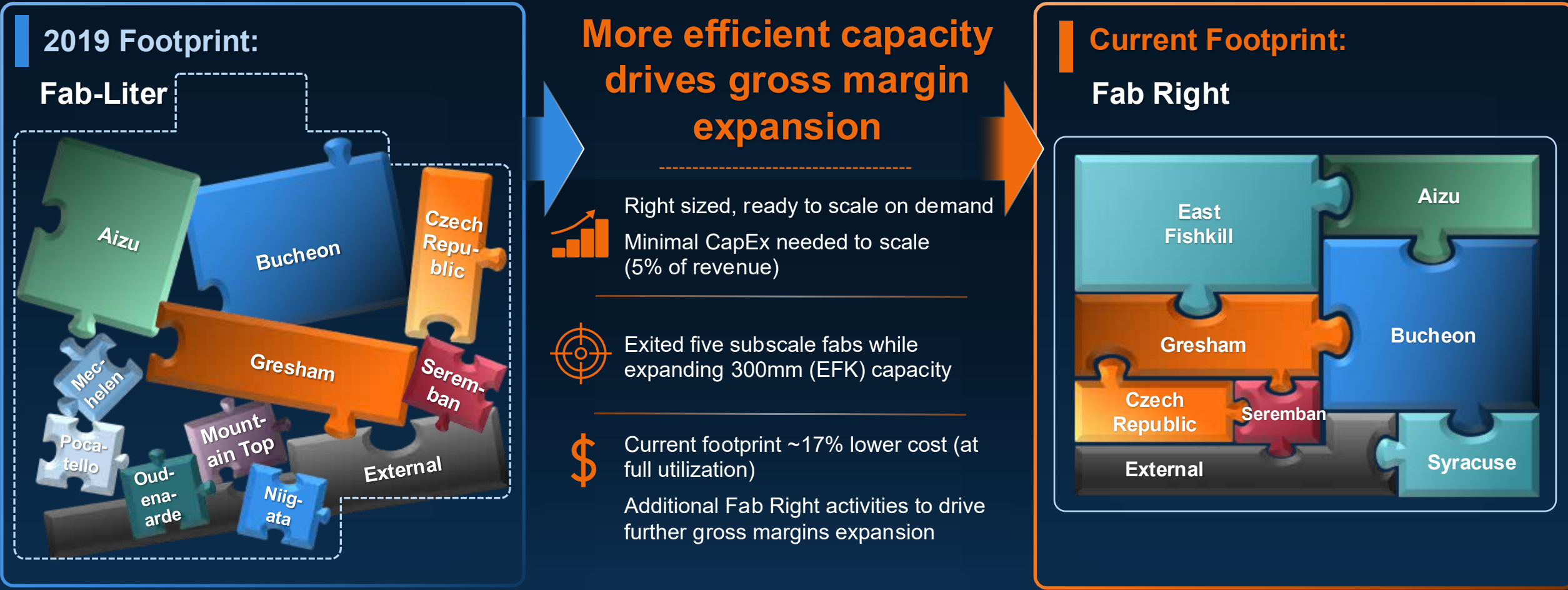
Broad global distribution network to serve the mass market

Top 20 customers represent ~35% of revenue, no 10% customer

Innovation and Portfolio Breadth Accelerates Growth



Fab Right: Building a More Efficient, Scalable Manufacturing Network

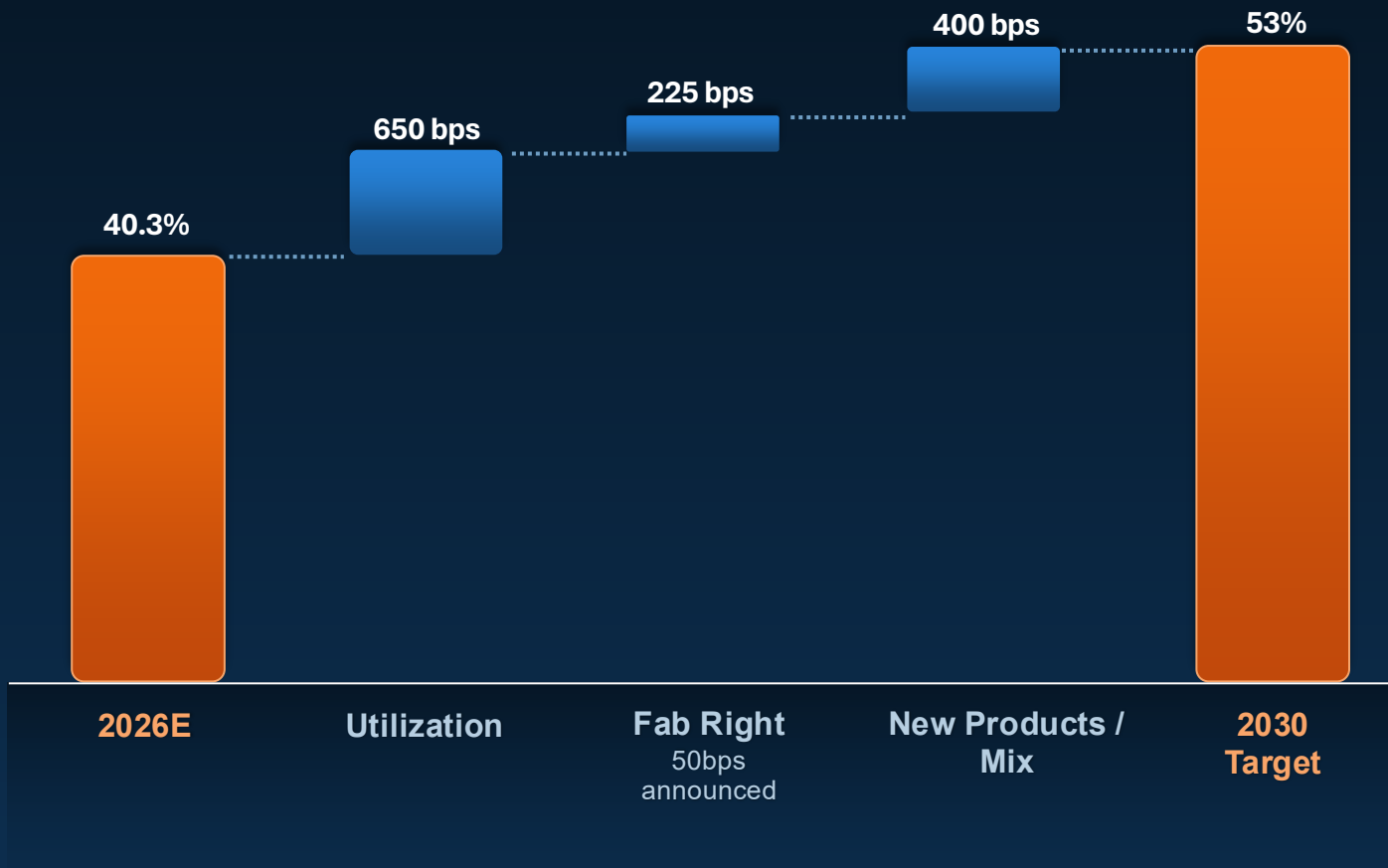


Scalable, Efficient, Lower Cost

Growth and Innovation Drive Gross Margin Expansion



Non-GAAP

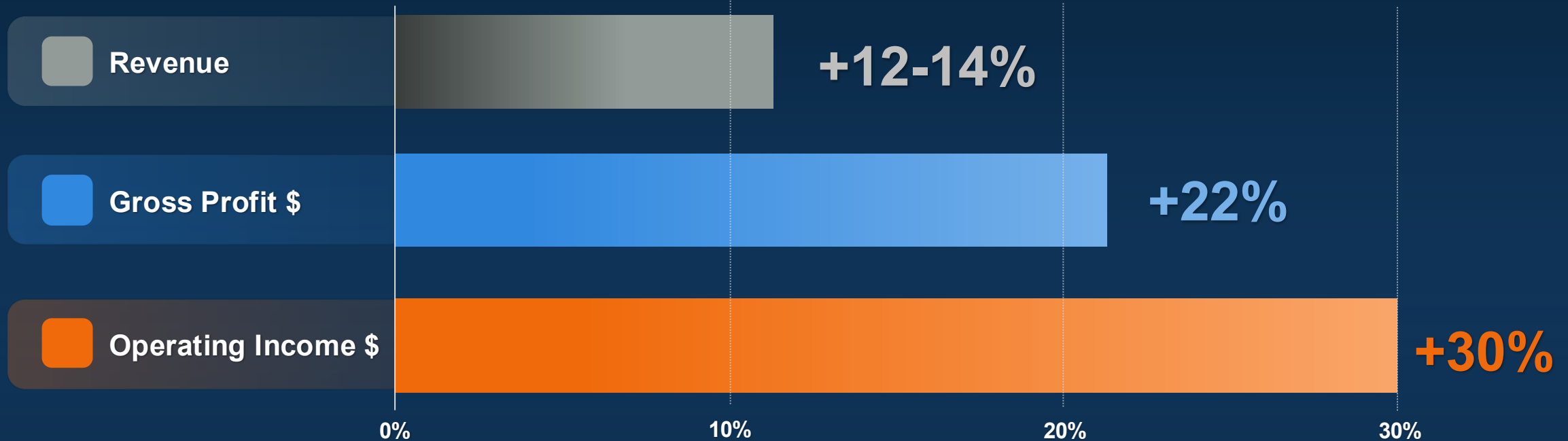


- Utilization**
 - Volume driven ramp to full utilization
 - Absorption of fixed costs
- Fab Right**
 - Additional efficiency and cost optimization
 - Capacity allocated to high value products
 - Two site divestitures recently announced
- New Products/ Mix**
 - Ramping differentiated products at accretive margins (Treo, EPP, vGaN)
 - Portfolio mix shift in silicon power products
 - Ramping high growth AI Data Center revenue

Top-line Growth → Outsized Earnings Growth

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Structural changes, innovation and execution deliver significant operating leverage



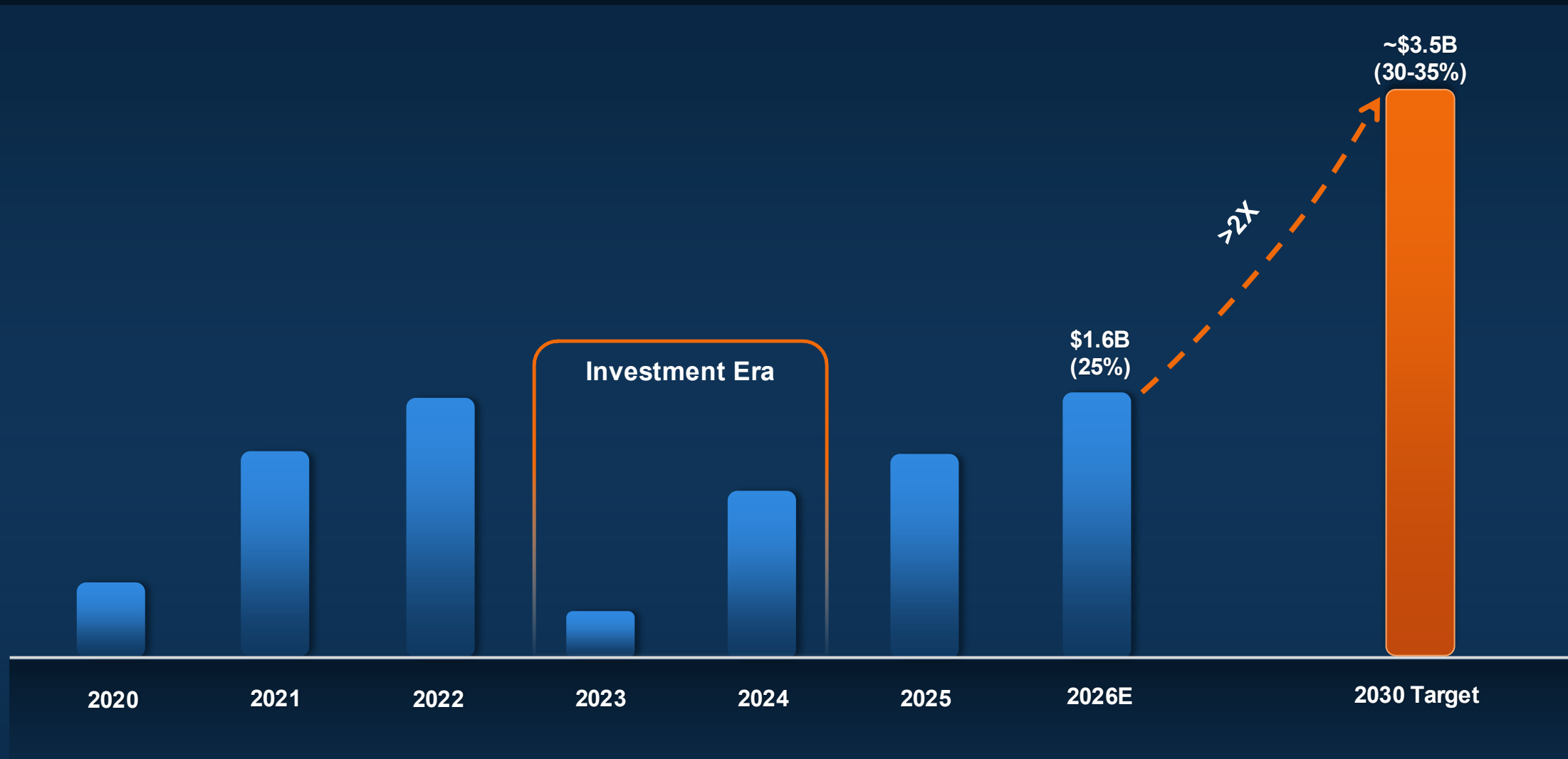
Non-GAAP CAGR, 2026E – 2030 Target

**Gross profit grows 1.6x faster than revenue;
operating income more than 2x faster.**

Free cash flow more than doubling by 2030



Monetizing Investments through scale and efficiency



2023-2026E: Share repurchase of \$4.2B, 92% of FCF → 12% reduction in shares

Disciplined Capital Allocation Compounds Shareholder Value



REINVEST

Fund the highest-return growth

Differentiated products, R&D and capacity investments that strengthen competitive advantage.



STRATEGIC M&A

Expand the portfolio selectively

Add capabilities to expand TAM and accelerate time to market. Clear strategic and financial merit enhancing the financial model.



BALANCE SHEET

Preserve resilience and flexibility

Maintain strong liquidity and leverage profile.



RETURN CASH

Repurchase shares consistently

Return 100% of free cash flow through share repurchases. \$5.3B remaining under the existing authorization.

Technology Leadership Powers Shareholder Value



Non-GAAP	2025A	2026E	2030 TARGET	
Revenue	\$6.0B	\$6.5B	+12-14% CAGR	Growth driven by highly differentiated products in fast growing markets
Gross Margin	38.4%	40.3%	53%	Utilization, high-value new products, and Fab Right
Operating Expenses	19.8%	18.5%	15%	Targeted R&D investment to expand capabilities and TAM
Operating Margin	18.6%	21.9%	38%	Operating income grows >2x revenue growth
CapEx	5.7%	2.7%	~5%	CapEx-light model for optimal capital allocation
Free Cash Flow	23.7%	24.8%	30-35%	Monetizing investments through scale and efficiency

Non-GAAP tax rate remains at 15% through 2030

Synaptics Accelerates Financial Model



Non-GAAP

Synaptics
Standalone
Post-Synergies

Revenue	>15%	Leverage onsemi sales channel to broaden customer base, increase content per platform, cross selling. Increases TAM by \$30B
Gross Margin	>55%	Connected-compute capabilities at accretive gross margins
Operating Margin	>30%	Accretive to EPS within ~18 months with \$200M of synergies

Technology Leadership Powers Shareholder Value



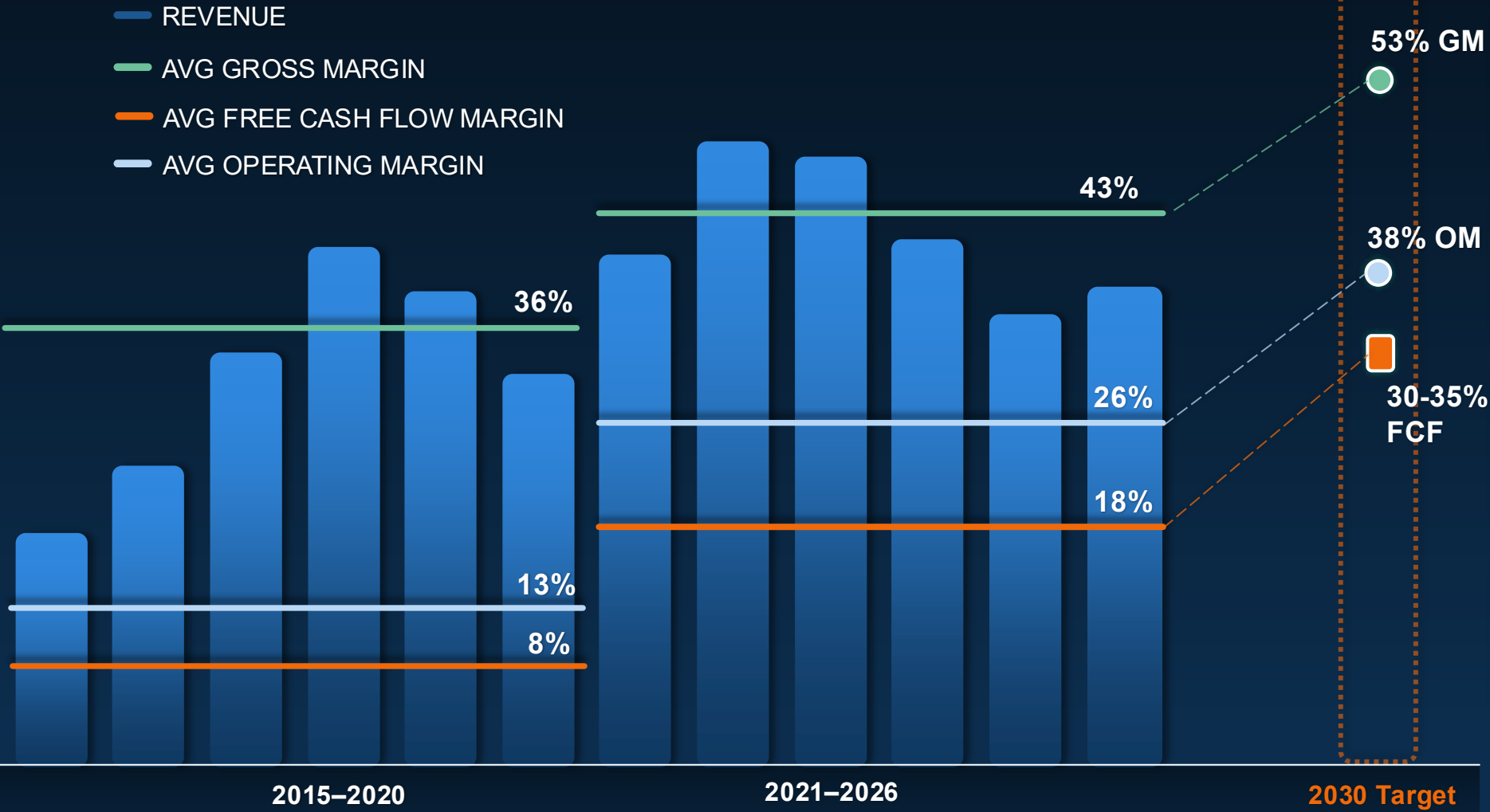
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Non-GAAP tax rate remains at 15% through 2030

The Power of onsemi's Transformation



Non-GAAP



- Accelerated growth, differentiated portfolio investments and Fab Right for gross margin expansion
- Streamlined manufacturing structure and OpEx efficiency drive significant operating leverage
- Leveraging past investments and capacity expansion support strong cash conversion
- Target operating margin is greater than legacy gross margins

Market Inflection. Differentiated Capabilities. Shareholder Value Creation.

onsemi

HIGH-VALUE, SECULAR MARKETS

AI data center, automotive, industrial

AI Data Center

Higher compute power driving a shift to high-voltage architectures and greater onsemi content.

Automotive

Electrification, autonomy and SDV/zonal architectures sustain content growth above SAAR.

Industrial

AI Halo driving power semi demand; physical AI emerging as a new onsemi growth vector.

DIFFERENTIATED CAPABILITIES

Differentiated technology expands margins

Unmatched breadth

A full LV and HV portfolio across silicon, SiC, GaN and vGaN.

Advanced platforms, exclusive to onsemi

Treo and EPP create differentiated power systems with best-in-class performance.

Scaled investment

\$8.7B invested over five years expands the addressable market by \$81B.

COMPOUNDING FINANCIALS

Non-GAAP · 2026E → 2030 Target

+12–14%

Revenue CAGR

53%

Gross margin expansion

38%

Operating margin expansion increases >2× revenue

30–35%

Free cash flow margin expansion to ~\$3.5B

Expanding markets + differentiated capabilities + disciplined execution = durable, profitable growth



Intelligent Technology. Better Future.

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onsemi.com

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APPENDIX

Appendix – GAAP to Non-GAAP Reconciliation

Reconciliation of GAAP to Non-GAAP Gross Margin						
Fiscal Year	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
GAAP Gross Margin	34.1%	33.2%	36.7%	38.1%	35.8%	32.7%
a) Amortization of fair market value step-up of inventory	0.0%	1.7%	0.2%	0.0%	0.4%	0.0%
b) Actuarial (gains)/losses on pension plans	0.0%	0.1%	0.0%	0.0%	0.0%	0.0%
c) Sell-through / sell-in adjustment	0.0%	0.0%	0.1%	0.0%	0.0%	0.0%
Non-GAAP Gross Margin	34.1%	35.0%	37.0%	38.1%	36.1%	32.7%

Fiscal Year	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
GAAP Gross Margin	40.3%	49.0%	47.1%	45.4%	33.1%
a) Impact of business wind down	0.0%	0.2%	0.0%	0.0%	0.0%
b) Amortization of acquisition-related intangible assets	0.0%	0.1%	0.1%	0.1%	0.1%
c) Non-recurring facility costs	0.1%	0.0%	0.0%	0.0%	0.0%
d) Restructuring-related inventory and other charges	0.0%	0.0%	0.0%	0.0%	5.2%
Non-GAAP Gross Margin	40.4%	49.2%	47.1%	45.5%	38.4%

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

Reconciliation of GAAP to Non-GAAP Operating Margin						
Fiscal Year	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
GAAP Operating Margin	7.5%	6.0%	12.3%	14.4%	7.8%	6.6%
a) Amortization of acquisition-related intangible assets	3.9%	2.7%	2.2%	1.9%	2.1%	2.3%
b) Restructuring, asset impairments and other, net	0.3%	0.8%	0.4%	0.1%	0.5%	1.2%
c) Goodwill and intangible asset impairment	0.1%	0.1%	0.2%	0.1%	0.0%	0.0%
d) Third party acquisition and divestiture-related costs	0.1%	0.7%	0.1%	0.1%	0.2%	0.0%
e) Amortization of fair market value step-up of inventory	0.0%	1.7%	0.2%	0.0%	0.4%	0.0%
f) Litigation settlement	0.0%	0.0%	0.0%	0.0%	3.1%	0.0%
g) Actuarial (gains)/losses on pension plans	-0.1%	0.3%	0.0%	0.0%	0.0%	0.0%
h) Sell-through / sell-in adjustment	0.0%	0.0%	-0.7%	0.0%	0.0%	0.0%
i) R&D costs related to licensing income	0.0%	0.0%	0.2%	0.1%	0.0%	0.0%
Non-GAAP Operating Margin	11.7%	12.3%	15.0%	16.7%	14.1%	10.2%

Fiscal Year	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
GAAP Operating Margin	19.1%	28.3%	30.8%	25.0%	1.4%
a) Amortization of acquisition-related intangible assets	1.5%	1.0%	0.7%	0.8%	0.8%
b) Restructuring, asset impairments and other, net	1.1%	0.2%	0.9%	1.9%	11.1%
c) Goodwill and intangible asset impairment	0.0%	4.6%	0.0%	0.0%	0.0%
d) Third party acquisition and divestiture-related costs	0.2%	0.2%	0.0%	0.2%	0.1%
e) Non-recurring facility costs	0.1%	0.0%	0.0%	0.0%	0.0%
f) Impact of business wind down	0.0%	0.2%	0.0%	0.0%	0.0%
g) Restructuring-related inventory and other charges	0.0%	0.0%	0.0%	0.0%	5.2%
Non-GAAP Operating Margin	21.9%	34.5%	32.3%	27.9%	18.6%

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

(in millions, except percentages)

Reconciliation of GAAP to Non-GAAP Operating Expenses	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
GAAP Operating Expenses	\$ 932.1	\$ 1,060.8	\$ 1,352.9	\$ 1,391.5	\$ 1,540.9	\$ 1,367.1
a) Amortization of acquisition-related intangible assets	(135.7)	(104.8)	(123.8)	(111.7)	(115.2)	(120.3)
b) Restructuring, asset impairments and other, net	(9.3)	(33.2)	(20.8)	(4.3)	(28.7)	(65.2)
c) Goodwill & intangible asset impairment	(3.8)	(2.2)	(13.1)	(6.8)	(1.6)	(1.3)
d) Third-party acquisition/divestiture costs	(3.5)	(25.8)	(3.2)	(4.4)	(11.3)	(1.0)
e) Actuarial gains/(losses) pension	4.2	(6.8)	0.7	-	-	-
f) R&D costs related to licensing income	-	-	(10.0)	-	-	-
g) Litigation settlement	-	-	-	-	(169.5)	-
j) R&D costs related to licensing income	-	-	-	(7.0)	-	-
Non-GAAP Operating Expenses	\$ 784.0	\$ 888.0	\$ 1,182.7	\$ 1,257.3	\$ 1,214.6	\$ 1,179.3
Non-GAAP Operating Expense Margin	22.4%	22.7%	22.0%	21.4%	22.0%	22.4%

Reconciliation of GAAP to Non-GAAP Operating Income	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
GAAP Operating Income	\$ 261.1	\$ 236.1	\$ 680.9	\$ 847.2	\$ 432.7	\$ 348.7
a) Amortization of acquisition-related intangible assets	135.7	104.8	123.8	111.7	115.2	120.3
b) Restructuring, asset impairments and other, net	9.3	33.2	20.8	4.3	28.7	65.2
c) Goodwill & intangible asset impairment	3.8	2.2	13.1	6.8	1.6	1.3
d) Third-party acquisition/divestiture costs	3.5	25.8	3.2	4.4	11.3	1.0
g) Amortization of fair value inventory step-up	-	67.5	13.6	1.0	19.6	-
h) Actuarial gains/(losses) pension	(5.0)	10.0	1.9	-	-	-
i) Litigation settlement	-	-	-	-	169.5	-
l) sell-through to sell in adjustment	-	-	(59.0)	-	-	-
m) R&D costs related to licensing income	-	-	10.0	7.0	-	-
Non-GAAP Operating Income	\$ 408.4	\$ 479.6	\$ 808.3	\$ 982.4	\$ 778.6	\$ 536.5

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

(in millions, except percentages)

Reconciliation of GAAP to Non-GAAP Operating Expenses	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
GAAP Operating Expenses	\$ 1,426.7	\$ 1,717.2	\$ 1,344.8	\$ 1,448.4	\$ 1,899.7
a) Amortization of acquisition-related intangible assets	(99.0)	(81.2)	(51.1)	(52.0)	(44.4)
b) Restructuring, asset impairments and other, net	(71.4)	(17.9)	(74.9)	(133.9)	(666.9)
c) Goodwill & intangible asset impairment	(2.9)	(386.8)	-	-	-
d) Third-party acquisition/divestiture costs	(11.9)	(12.9)	1.3	(14.0)	(4.3)
e) Impact of business wind down	-	6.8	-	-	-
f) Adjustments to contingent consideration	-	-	-	-	1.3
Non-GAAP Operating Expenses	\$ 1,241.5	\$ 1,225.2	\$ 1,220.1	\$ 1,248.5	\$ 1,185.4
Non-GAAP Operating Expense Margin	18.4%	14.7%	14.8%	17.6%	19.8%

Reconciliation of GAAP to Non-GAAP Operating Income	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
GAAP Operating Income	\$ 1,287.6	\$ 2,360.0	\$ 2,538.7	\$ 1,767.7	\$ 84.2
a) Amortization of acquisition-related intangible assets	99.0	82.8	56.8	58.3	49.4
b) Restructuring, asset impairments and other, net	71.4	17.9	74.9	133.9	666.9
c) Goodwill & intangible asset impairment	2.9	386.8	-	-	-
d) Third-party acquisition/divestiture costs	11.9	12.9	(1.3)	14.0	4.3
e) Non-recurring facility costs	5.5	-	-	-	-
f) Impact of business wind down	-	12.7	(3.9)	-	-
g) Amortization of fair value inventory step-up	-	-	-	-	2.4
h) Restructuring-related inventory charges	-	-	-	-	313.6
o) Adjustments to contingent consideration	-	-	-	-	(1.3)
Non-GAAP Operating Income	\$ 1,478.3	\$ 2,873.1	\$ 2,665.2	\$ 1,973.9	\$ 1,119.5

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation



(in millions, except percentages)

Reconciliation of net cash provided by operating activities to free cash flow						
Fiscal Year	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
Net cash provided by operating activities	\$ 470.6	\$ 581.2	\$ 1,094.2	\$ 1,274.2	\$ 694.7	\$ 884.3
Purchase of property, plant & equipment	\$ (272.2)	\$ (108.9)	\$ (395.7)	\$ (514.8)	\$ (534.6)	\$ (383.6)
Free Cash Flow	\$ 198.4	\$ 472.3	\$ 698.5	\$ 759.4	\$ 160.1	\$ 500.7
Free Cash Flow Margin	5.7%	12.1%	13.0%	13.0%	2.9%	9.5%

Reconciliation of net cash provided by operating activities to free cash flow	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
Net cash provided by operating activities	\$ 1,782.0	\$ 2,633.1	\$ 1,977.5	\$ 1,906.4	\$ 1,759.8
Purchase of property, plant & equipment	\$ (444.6)	\$ (1,005.0)	\$ (1,575.6)	\$ (694.0)	\$ (341.2)
Free Cash Flow	\$ 1,337.4	\$ 1,628.1	\$ 401.9	\$ 1,212.4	\$ 1,418.6
Free Cash Flow Margin	19.8%	19.6%	4.9%	17.1%	23.7%

Certain amounts in the above tables may not total due to rounding of individual amounts.

Charting a Path to Power the Next Decade of Innovation

Hassane El-Khoury, President and CEO

\$5.3B remaining under the existing authorization.

- As reported through Q2'2026

2026 estimates are based on consensus

onsemi: Powering the AI Revolution

Achyut Shah, Group President, Power Solutions Group

GPU Rack Power (kW per Rack) vs Deployment Horizon Graph

- McKinsey & Company – *The shift to 800-volt DC at data centers: Implications for providers*, published July 2026

Cumulative New Data Center Power Consumption Graph

- Bank of America-Watts to Token, May 2026

AI DC TAM CAGRs

- UB, Bank of America, Citi Bank, Mizuho and onsemi internal estimates

2026 estimates are based on consensus

Expanding the Core: Automotive and Industrial

Sudhir Gopalswamy, Group President, Analog & Mixed-Signal and Intelligent Sensing Groups

~0% SAAR 2019-26, 2026-2030

- Bloomberg Auto SAAR Factset 26E (0.39%)

Physical AI: \$6B TAM in 2030

- onsemi estimates, Yole, Omdia projections for: Autonomous Mobile Robots, Drones, Humanoid

2026 estimates are based on consensus

Turning Technology Leadership into Durable Financial Performance

Thad Trent, Executive Vice President and CFO

What you are used to seeing (images)

- Maximize Market Research Pvt. Ltd
- Deloitte and Mordor Intelligence
- KBV Research
- Yole

Sustainable Ecosystem '22-'27 TAM CAGRs

- onsemi estimates
- LMC Automotive: Global Hybrid & Electric Vehicle Forecast - Quarter 4, 2022
- Omdia: Power IC Market Tracker, Sep'22

Sustainable Ecosystem Accelerating onsemi Content

- Based on total onsemi BOM opportunity

Markets that Matter

- onsemi estimates based on current market projections
- Semiconductor TAM excludes Memory

Winning Formula...and Execute

- >\$17B: onsemi Form 10-Q filing for period ended March 31 2023

2026 estimates are based on consensus

Cautionary Information



No Offer or Solicitation

This communication is for informational purposes only and does not constitute, or form a part of, an offer to buy or sell or the solicitation of an offer to buy or sell any securities, or a solicitation of any vote or approval, nor shall there be any sale of securities in any jurisdiction in which such offer, solicitation or sale would be unlawful prior to registration or qualification under the securities laws of any such jurisdiction. No offer of securities shall be made except by means of a prospectus meeting the requirements of Section 10 of the Securities Act of 1933, as amended.

Important Additional Information about the Transaction and Where To Find It

The proposed transaction will be submitted to the stockholders of Synaptics for their consideration. In connection with the proposed transaction, on August 21, 2026, onsemi filed with the SEC a Registration Statement on Form S-4 that included a proxy statement of Synaptics and that also constituted a prospectus of onsemi. Each of Synaptics and onsemi will provide the proxy statement/prospectus to Synaptics stockholders. These materials are not yet final and will be amended. Synaptics and onsemi also plan to file other documents with the SEC regarding the proposed transaction. This document is not a substitute for any prospectus, proxy statement or any other document which Synaptics or onsemi may file with the SEC in connection with the proposed transaction. INVESTORS AND SECURITY HOLDERS ARE URGED TO READ THE PROXY STATEMENT/PROSPECTUS AND ANY OTHER RELEVANT DOCUMENTS THAT WILL BE FILED WITH THE SEC CAREFULLY AND IN THEIR ENTIRETY WHEN THEY BECOME AVAILABLE BECAUSE THEY WILL CONTAIN IMPORTANT INFORMATION ABOUT THE PROPOSED TRANSACTION. You may obtain copies of all documents filed with the SEC regarding this transaction, free of charge, at the SEC's website (www.sec.gov). In addition, investors and stockholders will be able to obtain free copies of the proxy statement/prospectus and other documents filed with the SEC by the parties on Synaptics Investor Relations at <https://investor.synaptics.com/> (for documents filed with the SEC by Synaptics) or onsemi Investor Relations at <https://investor.onsemi.com/> (for documents filed with the SEC by onsemi).

Cautionary Information



Participants in the Solicitation

Synaptics, onsemi, and certain of their respective directors, executive officers and other members of management and employees, under SEC rules may be deemed to be participants in the solicitation of proxies from Synaptics stockholders in connection with the proposed transaction. Information regarding the persons who may, under the rules of the SEC, be deemed participants in the solicitation of Synaptics stockholders in connection with the proposed transaction, and a description of their direct and indirect interests, by security holdings or otherwise, will be set forth in the proxy statement/prospectus that will be provided to Synaptics stockholders. You can find more detailed information about Synaptics' executive officers and directors under the headings "Proposal 1 – Election of Directors," "Director Compensation," "Compensation Discussion and Analysis," "Named Executive Officer Compensation Tables," "CEO Pay Ratio Disclosure," "Pay Versus Performance Disclosure" and "Beneficial Ownership of Certain Stockholders" in its definitive proxy statement filed with the SEC on September 16, 2025. To the extent holdings of Synaptics common stock by the directors and executive officers of Synaptics have changed from the amounts of Synaptics common stock held by such persons as reflected therein, such changes have been or will be reflected on Statements of Change in Ownership on Form 4 filed with the SEC, which are available at <https://www.sec.gov/edgar/browse/?CIK=817720&owner=exclude> under the tab "Ownership Disclosures". You can find more detailed information about onsemi's executive officers and directors under the headings "The Board of Directors and Corporate Governance," "Compensation of Executive Officers" and "Stock Ownership" in its definitive proxy statement filed with the SEC on April 2, 2026. To the extent holdings of onsemi common stock by the directors and executive officers of onsemi have changed from the amounts of onsemi common stock held by such persons as reflected therein, such changes have been or will be reflected on Statements of Change in Ownership on Form 4 filed with the SEC, which are available at <https://www.sec.gov/edgar/browse/?CIK=1097864&owner=exclude> under the tab "Ownership Disclosures". Additional information about Synaptics' executive officers and directors and onsemi's executive officers and directors can be found in the above-referenced Registration Statement on Form S-4.